BUF634A 36V、210MHz、250mA 输出高速缓冲器

1 特性

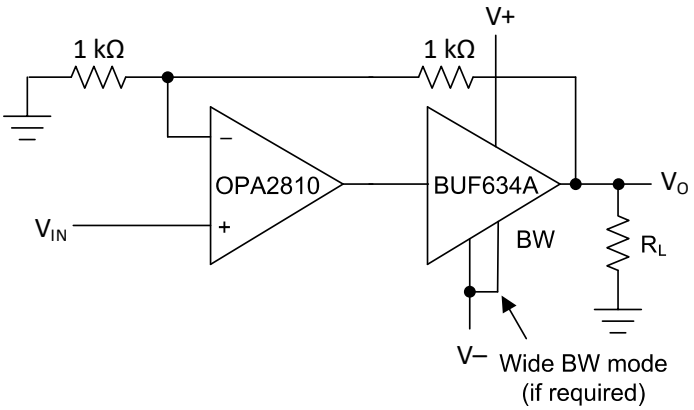
- 引脚选择带宽：35MHz 至 210MHz
- 高输出电流：250mA
- 压摆率：3750V/μs
- 低静态电流：1.5mA (35MHz BW)
- 宽电源电压范围：±2.25V 至 ±18V
- 内部输出电流限制
- 热关断保护
- 提供带散热焊盘的封装
- 工作温度范围：
  –40°C 至 +125°C

2 应用

- 存储器、半导体测试仪
- 测试设备
- 耳机驱动器
- 飞行控制系统
- 容性负载驱动器
- 阀驱动器、电磁驱动器
- 线路驱动器

3 说明

BUF634A 器件是一款高性能、高保真的开环缓冲器，能够驱动 250mA 的输出电流。BUF634A 是一款 36V 的器件，可通过改变 V– 与 BW 引脚之间的外部电阻器值在 35MHz 至 210MHz 范围内调节带宽。



提升任何运算放大器的输出电流

BUF634A 器件可用作独立开环驱动器，也可以在精密运算放大器的反馈环路内部使用，以便为高精度驱动器和大输出电流驱动器提供更高的容性负载驱动能力。

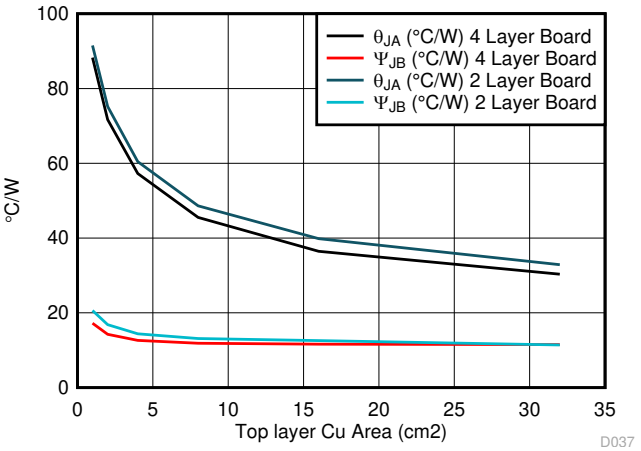
对于低功耗应用，BUF634A 器件具有 1.5mA 的工作静态电流以及 250mA 的输出、3750V/μs 的压摆率和 35MHz 带宽。此器件在带宽为 210MHz 的宽带宽模式下消耗 8.5mA 的静态电流。BUF634A 通过其输出级中的内部电流限制以及热关断受到全面保护，因而非常耐用且易于使用。

BUF634A 器件可在 –40°C 至 +125°C 的工业温度范围内正常运行。BUF634A 可采用三种封装：D (SOIC)、DRB (VSON) 和 DDA (HSOIC)。DRB (VSON) 和 DDA (HSOIC) 封装的底部具有散热焊盘，因此具有出色的热性能。DRB 封装的外形尺寸非常小，只有 3.0mm × 3.0mm，这使得该器件非常适合便携式和尺寸受限的应用。

器件信息(1)

器件型号	封装	封装尺寸（标称值）
BUF634A	SOIC (8)	4.90mm × 3.90mm
	VSON (8)	3.00mm × 3.00mm
	HSOIC (8)	4.90mm × 3.90mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



DDA 封装的热性能与覆铜面积之间的关系

本文档旨在为方便起见，提供有关 TI 产品中文版本的信息，以确认产品的概要。有关适用的官方英文版本的最新信息，请访问 www.ti.com，其内容始终优先。TI 不保证翻译的准确性和有效性。在实际设计之前，请务必参考最新版本的英文版本。

Table of Contents

1 特性 1
2 应用 1
3 说明 1
4 Revision History 2
5 Device Comparison Table 3
6 Pin Configuration and Functions 3
7 Specifications 4
7.1 Absolute Maximum Ratings 4
7.2 ESD Ratings 4
7.3 Recommended Operating Conditions 4
7.4 Thermal Information 4
7.5 Electrical Characteristics: Wide-Bandwidth Mode 5
7.6 Electrical Characteristics: Low-Quiescent Current Mode 6
7.7 Typical Characteristics 7
8 Detailed Description 13
8.1 Overview 13
8.2 Functional Block Diagram 13
8.3 Feature Description 14
8.4 Device Functional Modes 15
9 Application and Implementation 16
9.1 Application Information 16
9.2 Typical Application 18
10 Power Supply Recommendations 20
10.1 Power Dissipation and Thermal Considerations 20
11 Layout 21
11.1 Layout Guidelines 21
11.2 Layout Example 23
12 Device and Documentation Support 24
12.1 Device Support 24
12.2 Documentation Support 24
12.3 Receiving Notification of Documentation Updates 24
12.4 支持资源 24
12.5 Trademarks 24
12.6 Electrostatic Discharge Caution 25
12.7 Glossary 25
13 Mechanical, Packaging, and Orderable Information 25

4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision E (December 2020) to Revision F (May 2021) — **Page**

- 用 *DDA 封装的热性能与覆铜面积之间的关系* 图替换了*将 BUF634A 与 OPA2810 配合使用时 THD+N 与频率之间的关系 (V_O = 10V_{PP}，90kHz 测量带宽)* 图 1

Changes from Revision D (September 2020) to Revision E (December 2020) — **Page**

- 删除了针对 BUF634A VSON 封装的*预发布*声明 1
- Deleted *preview* statement for the DRB package 3

Changes from Revision C (June 2020) to Revision D (September 2020) — **Page**

- 更新了整个文档的表、图和交叉参考的编号格式 1
- Added DRB package outline to *Mechanical, Packaging, and Orderable Information* section 25

Changes from Revision B (January 2020) to Revision C (June 2020) — **Page**

- 删除了针对 BUF634A HSOIC 封装的*预发布*声明 1
- Deleted *preview* statement for the D and DDA packages 3

Changes from Revision A (May 2019) to Revision B (January 2020) — **Page**

- 向文档添加了 DRB (VSON) 和 DDA (HSOIC) 封装 1
- 更改了*应用*部分 1
- 更改了*说明*部分的最后一段 1
- Added discussion of V_{IN} pin to *ESD Protection* section 14
- Added *Power Dissipation and Thermal Considerations* section 20
- Added *HSOIC Layout Guidelines (DDA Package With a Thermal Pad)* section 22
- Changed title of *BUF634A Layout Example* image 23

Changes from Revision * (February 2019) to Revision A (May 2019) — **Page**

- 将文档状态从“预告信息”更改为“量产数据” 1

Copyright © 2021 Texas Instruments Incorporated

5 Device Comparison Table

DEVICE	V_S ± (V)	I_Q / CHANNEL (mA)	BW (MHz)	SLEW RATE (V/µs)	VOLTAGE NOISE (nV/√Hz)	AMPLIFIER DESCRIPTION
BUF634A	±18	1.5 – 8.5	35 – 210	3750	3.4	Unity-gain, open-loop buffer
BUF634	±18	1.5 – 15	30 – 180	2000	4	Unity-gain, open-loop buffer
LMH6321	±18	11	110	1800	2.8	Unity-gain, open-loop buffer with adjustable current limit

6 Pin Configuration and Functions

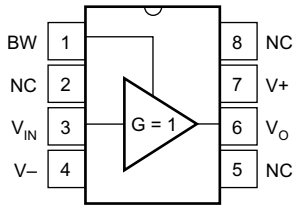


图 6-1. D and DDA Packages 8-Pin SOIC, 8-Pin HSOIC with Thermal Pad Top View

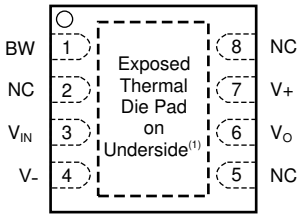


图 6-2. DRB Package 8-Pin VSON with Thermal Pad Top View

表 6-1. Pin Functions

PIN				I/O(2)	DESCRIPTION
NAME	DDA(1)	DRB(1)	D		
BW	1	1	1	I	Bandwidth adjust pin. Connect the BW pin to the V– pin for wide-BW mode and leave the BW pin floating for low-I_Q mode. See the *Adjustable Bandwidth* section.
NC	2, 5, 8	2, 5, 8	2, 5, 8	—	No internal connection
V–	4	4	4	P	Negative power supply
V+	7	7	7	P	Positive power supply
V_{IN}	3	3	3	I	Input
V_O	6	6	6	O	Output
Thermal Pad			—	—	Thermal pad. Must be electrically shorted to V–.

(1) The DRB and DDA packages include a thermal pad on the backside of the device. The thermal pad must be connected to the same potential as V–. Connect the thermal pad and V– to a heat-spreading plane to achieve low thermal impedance. The thermal pad can also be unused (not connected to any heat-spreading plane or voltage), thus giving an overall higher thermal impedance.
(2) I = input, O = output, P = power.

Copyright © 2021 Texas Instruments Incorporated

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
V_S = (V+) – (V–)	Supply voltage		40 (±20)	V
V_{IN}	Input voltage		Vs ± 0.5	V
	Output short-circuit (to ground)		Continuous	
T_A	Operating ambient temperature	–40	125	°C
T_J	Junction temperature		150	°C
T_{stg}	Storage temperature	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±3000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101(2)	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_S = (V+) – (V–)	Supply voltage	±2.25	±15	±18	V
T_A	Ambient temperature	–40	25	125(1)	°C

(1) Limited by $R_{\Theta JA}$ and $T_{J,Max}$ for safe operation. See the Output Current section.

7.4 Thermal Information

THERMAL METRIC(1)		BUF634A			UNIT
		D (SOIC)	DRB (VSON)	DDA (HSOIC)	
		8 PINS	8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	122.9	51	41.3	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	55.2	58	57.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	68.4	23.8	17.0	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	12.1	1.7	4.6	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	67.2	23.8	17.0	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	NA	9.0	5.3	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

Copyright © 2021 Texas Instruments Incorporated

7.5 Electrical Characteristics: Wide-Bandwidth Mode

at T_A = 25°C, V_S = ±15 V, BW pin connected to V –, and R_L = 100 Ω connected to mid-supply (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
AC PERFORMANCE						
BW	Bandwidth, –3 dB	R_L = 1 kΩ		210		MHz
		R_L = 100 Ω		200		
	Bandwidth for 0.1-dB flatness	V_O = 10 mV_{PP}, R_L = 100 Ω, R_S = 50 Ω		50		MHz
SR	Slew rate	V_O = 20-V step, V_{IN}-SR = 4000 V/µs		3750		V/µs
	Rise and fall time	V_O = 200-mV step		1.3		ns
	Settling time to 0.1%	V_O = 20-V step, V_{IN}-SR = 2500 V/µs		90		ns
	Settling time to 1%	V_O = 20-V step, V_{IN}-SR = 2500 V/µs		20		ns
e_n	Voltage noise	f = 1 kHz		3.4		nV/√Hz
i_n	Current noise	f = 100 kHz		0.85		pA/√Hz
HD2	2nd-harmonic distortion	V_O = 2 V_{PP}, f = 20 kHz		–77		dBc
		V_O = 10 V_{PP}, f = 20 kHz		–69		
HD3	3rd-harmonic distortion	V_O = 2 V_{PP}, f = 20 kHz		–77		dBc
		V_O = 10 V_{PP}, f = 20 kHz		–56		
DC PERFORMANCE						
V_{OS}	Input offset voltage	T_A = 25℃		36	65	mV
	Input offset voltage drift[1]	T_A = –40℃ to 125℃		175		µV/℃
I_B	Input bias current	V_{IN} = 0 V		0.25	2	µA
G	Gain	V_O = ±10 V, R_L = 1 kΩ	0.95	0.99		V/V
		V_O = ±10 V, R_L = 100 Ω	0.93	0.95		
		V_O = ±10 V, R_L = 67 Ω	0.91	0.93		
INPUT						
	Linear input voltage range	R_L = 1 kΩ, I_B < 10 µA	–13		13	V
Z_{IN}	Input impedance	R_L = 100 Ω		180 || 5		MΩ || pF
OUTPUT						
	Output headroom to supplies	I_O = ±10 mA		1.6	1.8	V
		I_O = ±100 mA		2.0	2.2	
		I_O = ±150 mA		2.2	2.5	
I_O	Current output, continuous			±250		mA
I_{SC}	Short-circuit current			±375	±550	mA
Z_O	Output impedance	DC, I_O = 10 mA		5		Ω
POWER SUPPLY						
V_S	Operating voltage range		±2.25		±18	V
I_Q	Quiescent current	I_O = 0 mA		8.5	12	mA
PSRR	Power-supply rejection ratio	V_S = ±2.25 V to ±18 V	64	75		dB
THERMAL SHUTDOWN						
	Thermal shutdown temperature			180		℃

(1) Based on electrical characterization over temperature of 35 devices.

Copyright © 2021 Texas Instruments Incorporated

7.6 Electrical Characteristics: Low-Quiescent Current Mode

at T_A = 25°C, V_S = ±15 V, BW pin left open, and R_L = 100 Ω connected to mid-supply (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
AC PERFORMANCE						
BW	Bandwidth, –3 dB	R_L = 1 kΩ		35		MHz
		R_L = 100 Ω		31		
	Bandwidth for 0.1-dB flatness	V_O = 10 mV_{PP}, R_L = 100 Ω, R_S = 50 Ω		2.3		MHz
SR	Slew rate	V_O = 20-V step, V_{IN}-SR = 4000 V/µs		3750		V/µs
	Rise and fall time	V_O = 200-mV step		4		ns
	Settling time to 0.1%	V_O = 20-V step, V_{IN}-SR = 2500 V/µs		400		ns
	Settling time to 1%	V_O = 20-V step, V_{IN}-SR = 2500 V/µs		90		ns
e_n	Voltage noise	f = 1 kHz		8.1		nV/√Hz
i_n	Current noise	f = 10 kHz		0.3		pA/√Hz
HD2	2nd-harmonic distortion	V_O = 2 V_{PP}, f = 20 kHz		–54		dBc
		V_O = 10 V_{PP}, f = 20 kHz		–65		
HD3	3rd-harmonic distortion	V_O = 2 V_{PP}, f = 20 kHz		–40		dBc
		V_O = 10 V_{PP}, f = 20 kHz		–44		
DC PERFORMANCE						
V_{OS}	Input offset voltage	T_A = 25℃		36	65	mV
	Input offset voltage drift(1)	T_A = –40℃ to 125℃		175		µV/℃
I_B	Input bias current	V_{IN} = 0 V		0.03	0.25	µA
G	Gain	V_O = ±10 V, R_L = 1 kΩ	0.95	0.99		V/V
		V_O = ±10 V, R_L = 100 Ω	0.93	0.95		
		V_O = ±10 V, R_L = 67 Ω	0.91	0.93		
INPUT						
	Linear input voltage range	R_L = 1 kΩ, I_B < 10 µA	–13		13	V
Z_{IN}	Input impedance	R_L = 100 Ω		1400 || 5		MΩ || pF
OUTPUT						
	Output headroom to supplies	I_O = ±10 mA		1.6	1.8	V
		I_O = ±100 mA		2.0	2.2	
		I_O = ±150 mA		2.2	2.5	
I_O	Current output, continuous			±250		mA
I_{SC}	Short-circuit current			±350	±550	mA
Z_O	Output impedance	DC, I_O = 10 mA		7		Ω
POWER SUPPLY						
V_S	Operating voltage range		±2.25		±18	V
I_Q	Quiescent current	I_O = 0		1.5	2.3	mA
PSRR	Power-supply rejection ratio	V_S = ±2.25 V to ±18 V	64	80		dB
THERMAL SHUTDOWN						
	Thermal shutdown temperature			180		℃

(1) Based on electrical characterization over temperature of 35 devices.

Copyright © 2021 Texas Instruments Incorporated

7.7 Typical Characteristics

At T_A = 25°C, V_S = ±15 V, R_S = 50 Ω, and R_L = 100 Ω (unless otherwise noted).

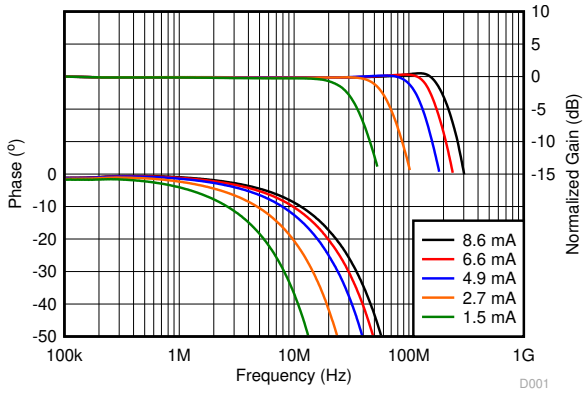
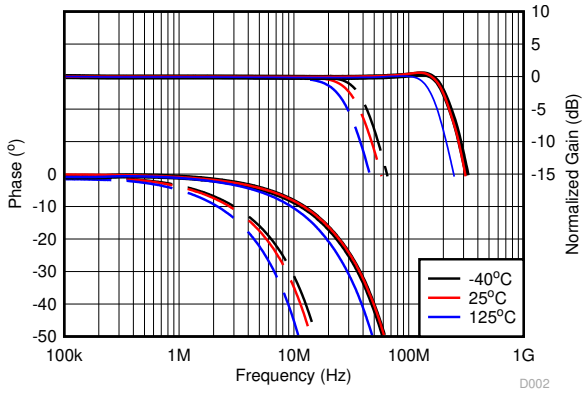
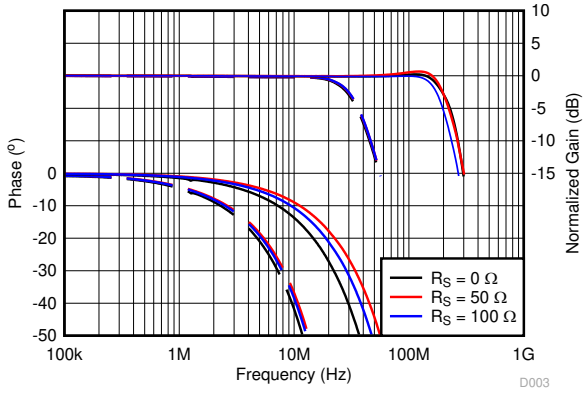


图 7-1. Gain and Phase vs Frequency and Quiescent Current



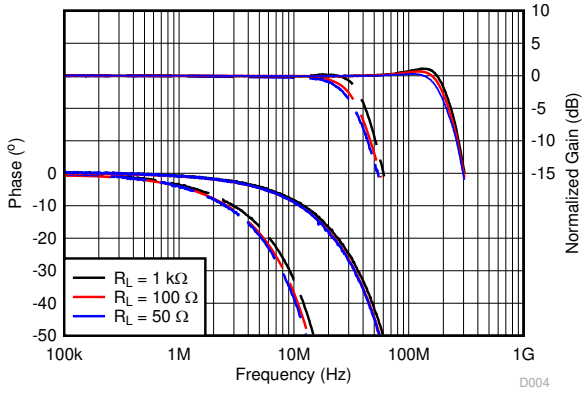
Solid lines indicate wide-BW mode, dashed lines indicate low-I_Q mode

图 7-2. Gain and Phase vs Frequency and Temperature



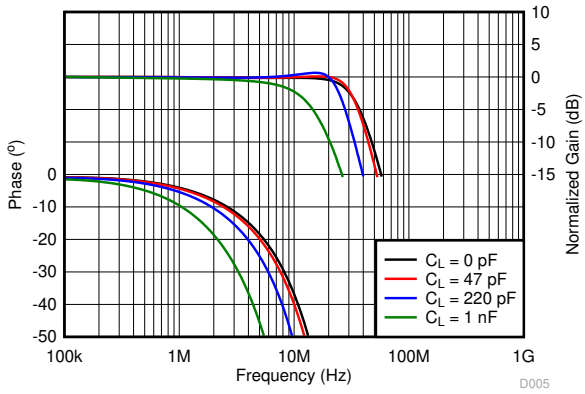
Solid lines indicate wide-BW mode, dashed lines indicate low-I_Q mode

图 7-3. Gain and Phase vs Frequency and Source Resistance



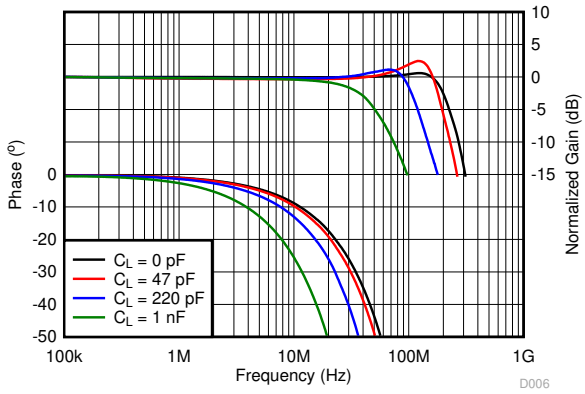
Solid lines indicate wide-BW mode, dashed lines indicate low-I_Q mode

图 7-4. Gain and Phase vs Frequency and Load Resistance



Low-I_Q mode

图 7-5. Gain and Phase vs Frequency and Load Capacitance



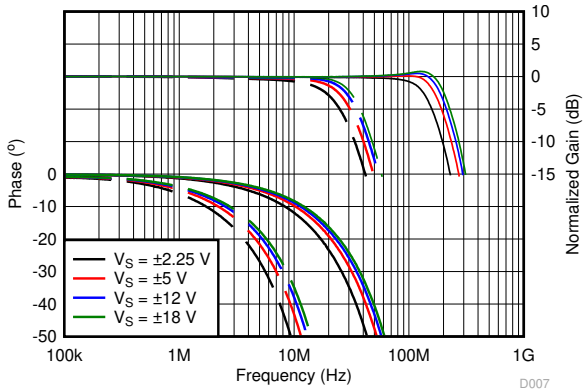
Wide-BW mode

图 7-6. Gain and Phase vs Frequency and Load Capacitance

Copyright © 2021 Texas Instruments Incorporated

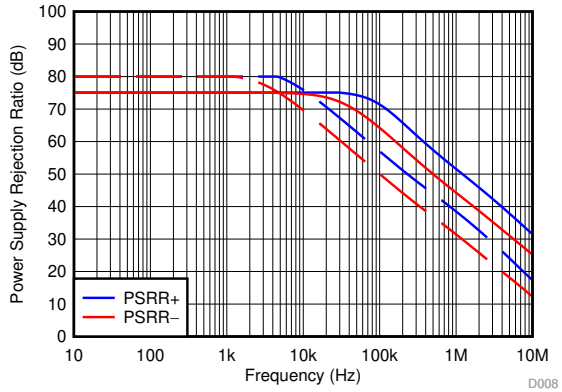
7.7 Typical Characteristics (continued)

At T_A = 25°C, V_S = ±15 V, R_S = 50 Ω, and R_L = 100 Ω (unless otherwise noted).



Solid lines indicate wide-BW mode, dashed lines indicate low-I_Q mode

图 7-7. Gain and Phase vs Frequency and Power-Supply Voltage



Solid lines indicate wide-BW mode, dashed lines indicate low-I_Q mode

图 7-8. PSRR vs Frequency

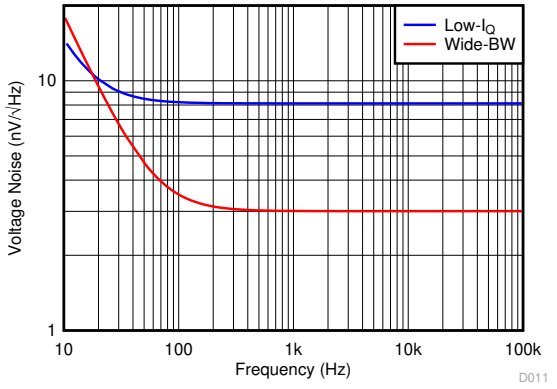


图 7-9. Voltage Noise Density vs Frequency

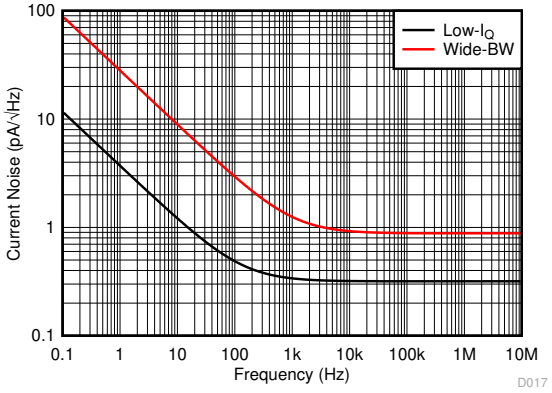
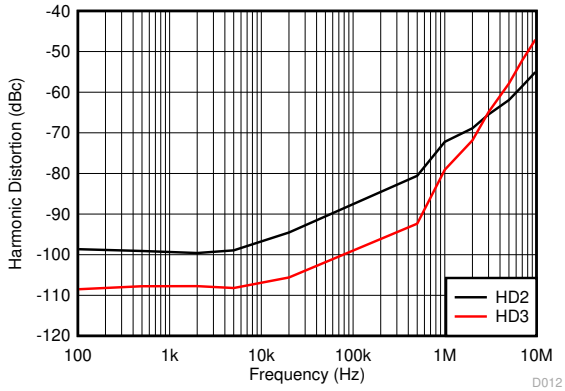
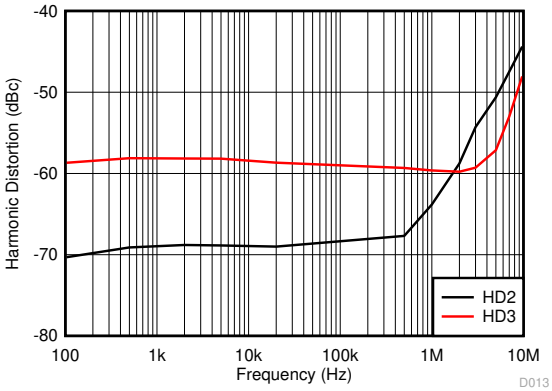


图 7-10. Current Noise Density vs Frequency



Wide-BW mode, V_{IN} = 10 V_{PP}, R_L = 1 kΩ

图 7-11. Harmonic Distortion vs Frequency



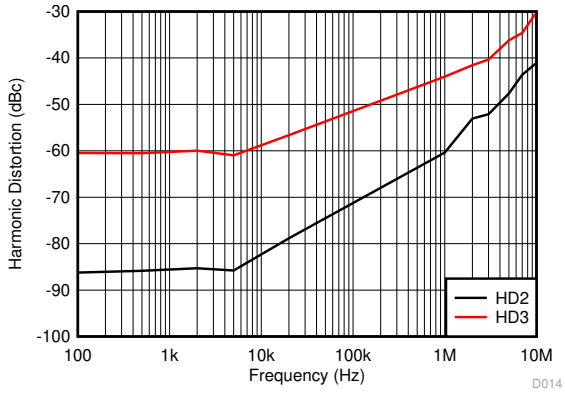
Wide-BW mode, V_{IN} = 10 V_{PP}, R_L = 100 Ω

图 7-12. Harmonic Distortion vs Frequency

Copyright © 2021 Texas Instruments Incorporated

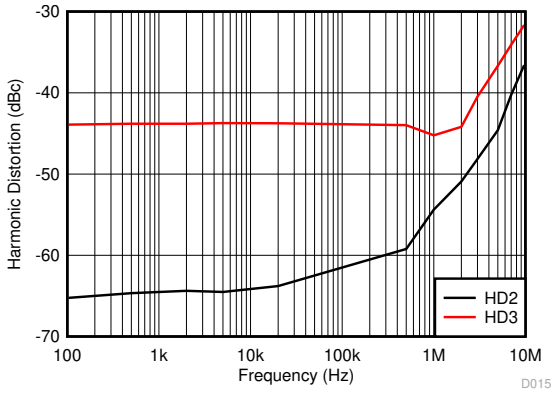
7.7 Typical Characteristics (continued)

At T_A = 25°C, V_S = ±15 V, R_S = 50 Ω, and R_L = 100 Ω (unless otherwise noted).



Low-I_Q mode, V_{IN} = 10 V_{PP}, R_L = 1 kΩ

图 7-13. Harmonic Distortion vs Frequency



Low-I_Q mode, V_{IN} = 10 V_{PP}, R_L = 100 Ω

图 7-14. Harmonic Distortion vs Frequency

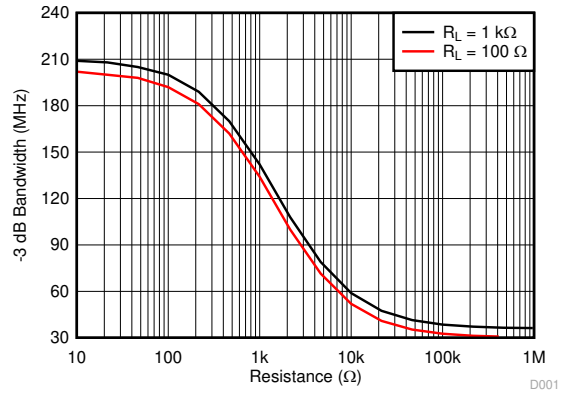


图 7-15. Small-Signal Bandwidth vs Bandwidth Adjustment Resistance

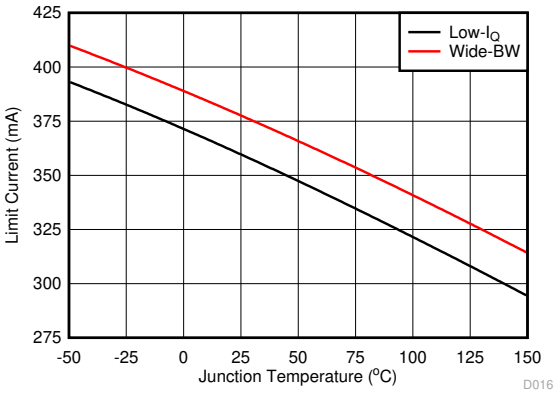
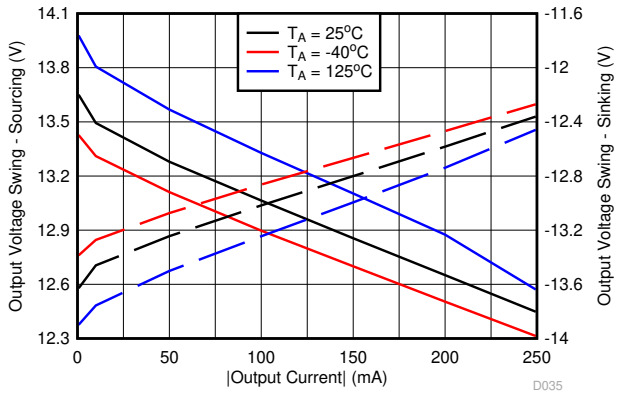
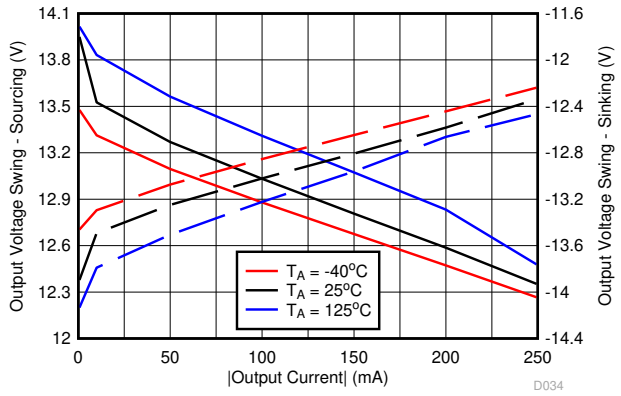


图 7-16. Short-Circuit Current vs Temperature



Wide-BW mode (solid lines indicate sourcing current, dashed lines indicate sinking current)

图 7-17. Output Voltage Swing vs Output Current



Low-I_Q mode (solid lines indicate sourcing current, dashed lines indicate sinking current)

图 7-18. Output Voltage Swing vs Output Current

7.7 Typical Characteristics (continued)

At T_A = 25°C, V_S = ±15 V, R_S = 50 Ω, and R_L = 100 Ω (unless otherwise noted).

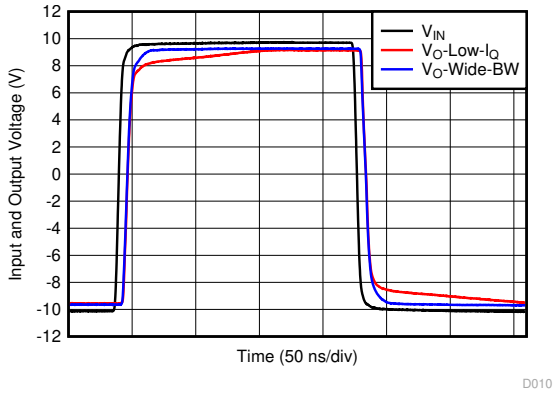


图 7-19. Large-Signal Transient Response

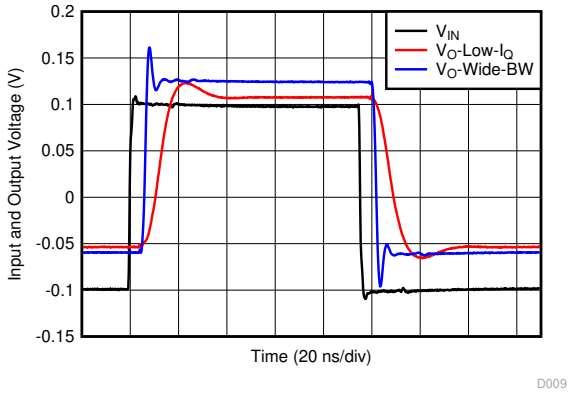
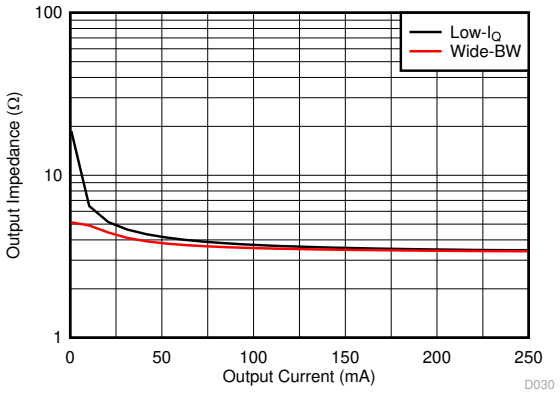
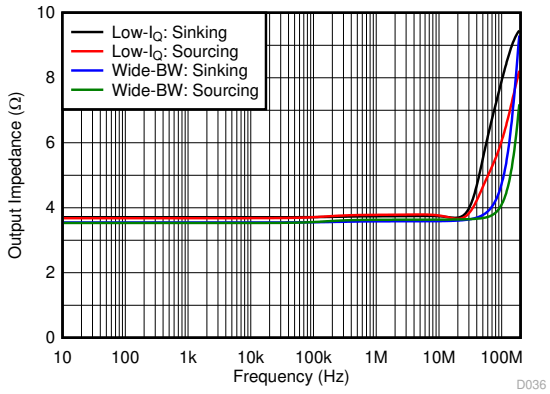


图 7-20. Small-Signal Transient Response



f = 100 kHz

图 7-21. Output Impedance vs Output Current



I_O = 100 mA

图 7-22. Output Impedance vs Frequency

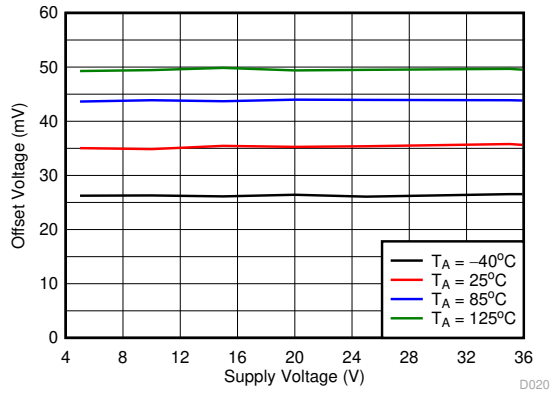
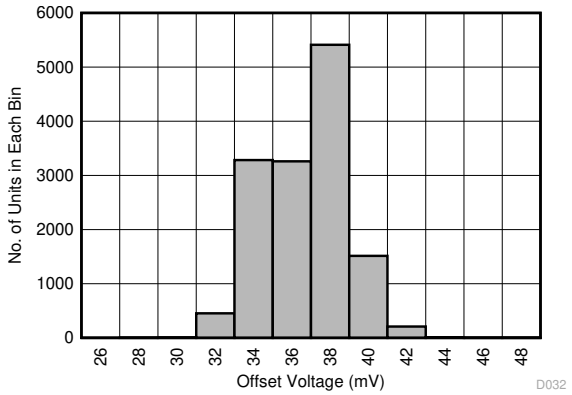


图 7-23. Offset Voltage vs Supply Voltage



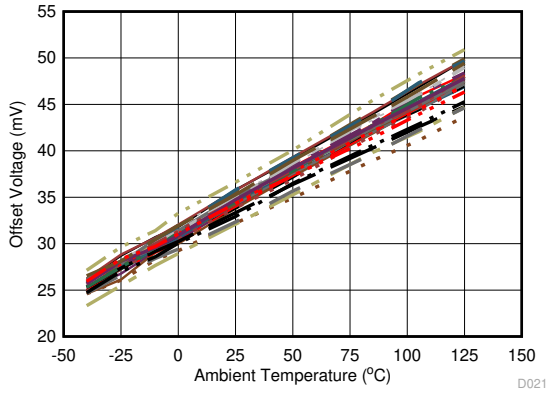
14000 devices, μ = 35.7 mV, σ = 2.15 mV

图 7-24. Offset Voltage Distribution Histogram

Copyright © 2021 Texas Instruments Incorporated

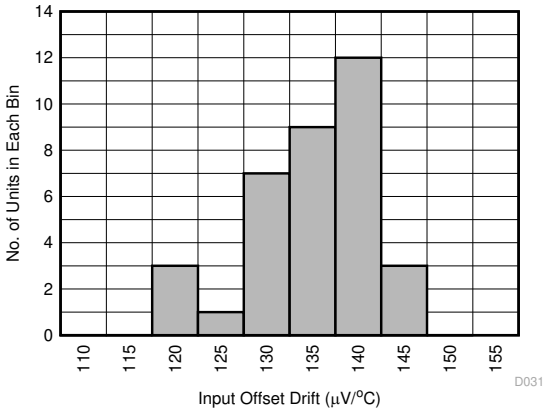
7.7 Typical Characteristics (continued)

At T_A = 25°C, V_S = ±15 V, R_S = 50 Ω, and R_L = 100 Ω (unless otherwise noted).



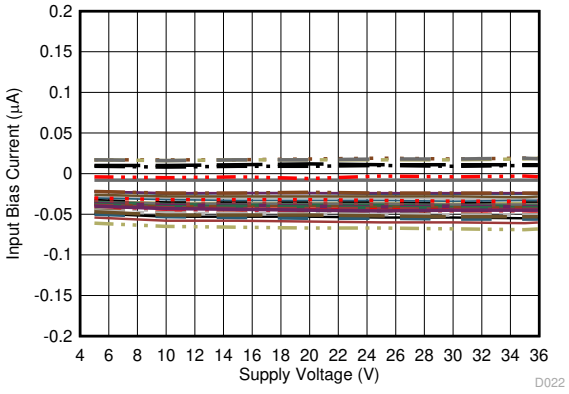
35 devices

图 7-25. Offset Voltage vs Temperature



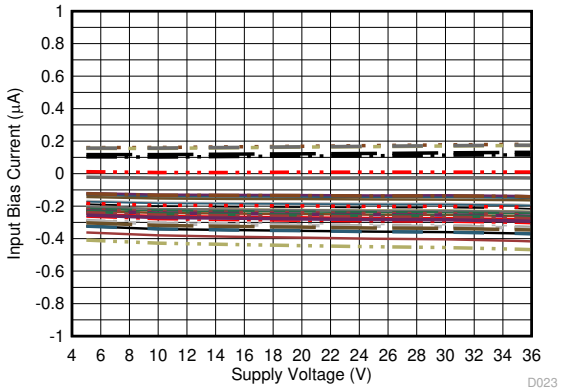
T_A = –40°C to +125°C, 35 devices, µ = 134 µV/°C, σ = 7.4 µV/°C

图 7-26. Offset Voltage Drift Distribution Histogram



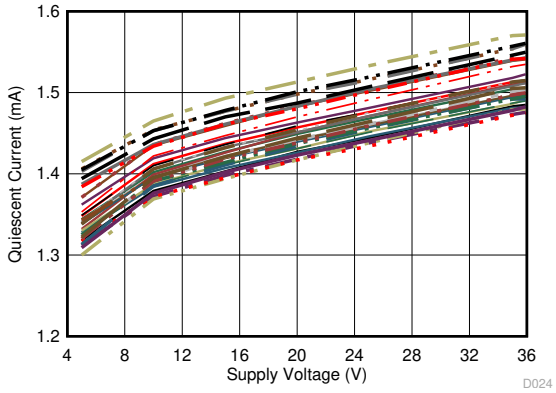
Low-I_Q mode, 35 devices

图 7-27. Input Bias Current vs Supply Voltage



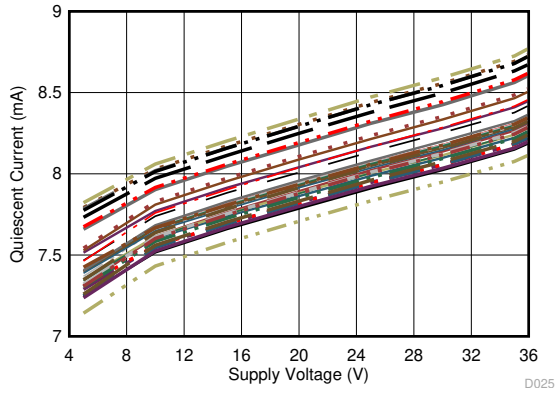
Wide-BW mode, 35 devices

图 7-28. Input Bias Current vs Supply Voltage



Low-I_Q mode, 35 devices

图 7-29. Quiescent Current vs Supply Voltage



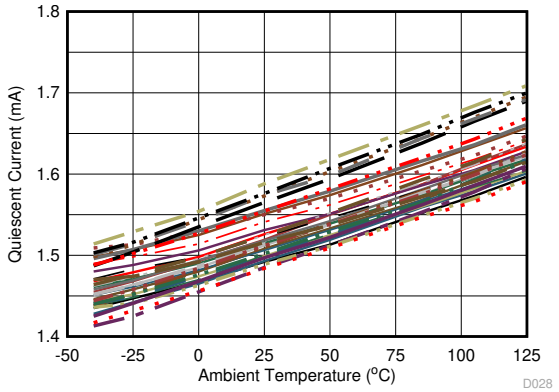
Wide-BW mode, 35 devices

图 7-30. Quiescent Current vs Supply Voltage

Copyright © 2021 Texas Instruments Incorporated

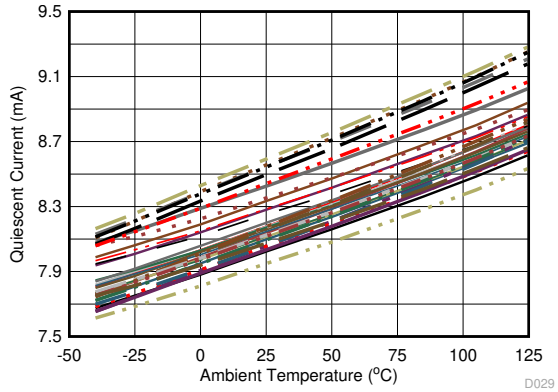
7.7 Typical Characteristics (continued)

At T_A = 25°C, V_S = ±15 V, R_S = 50 Ω, and R_L = 100 Ω (unless otherwise noted).



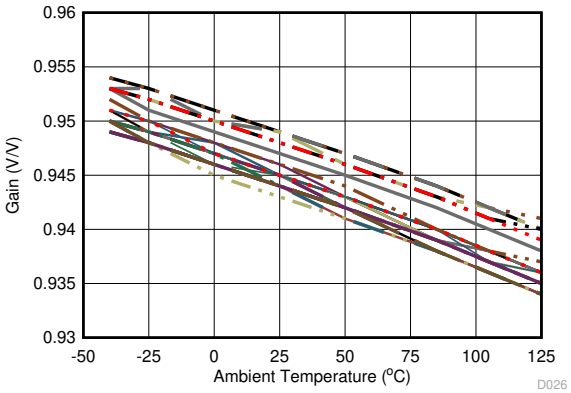
Low-I_Q mode, 35 devices

图 7-31. Quiescent Current vs Temperature



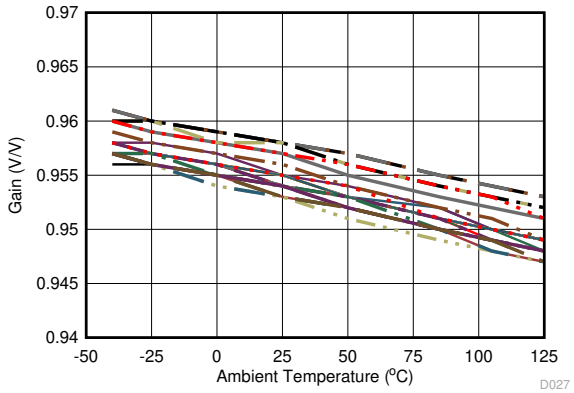
Wide-BW mode, 35 devices

图 7-32. Quiescent Current vs Temperature



Low-I_Q mode, 35 devices

图 7-33. Buffer Gain vs Temperature



Wide-BW mode, 35 devices

图 7-34. Buffer Gain vs Temperature

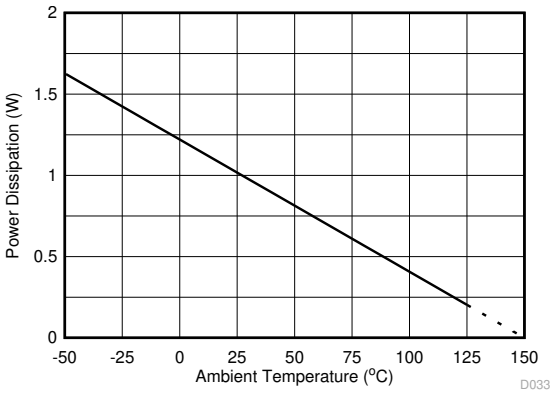


图 7-35. Maximum Power Dissipation vs Temperature

Copyright © 2021 Texas Instruments Incorporated

8 Detailed Description

8.1 Overview

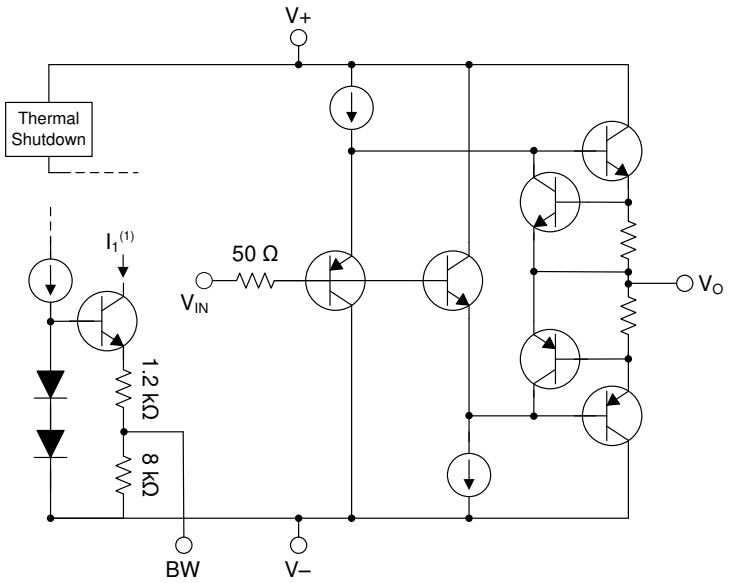
The BUF634A device is a high-speed, unity-gain, open-loop buffer that can be used in a wide range of applications requiring large output current drive or large slew rates. The BUF634A can operate on power supplies ranging from 4.5 V to 36 V and includes an internal output current limiting feature and thermal shutdown, thereby making the device rugged and easy to use.

The bandwidth of the BUF634A can be adjusted by connecting a resistor between the V – and BW pins. Its power scaling with bandwidth makes the device suitable for use in portable battery-powered applications. See the *节 8.4.1* for a description of the relationship between bandwidth adjustment resistance and the device –3-dB bandwidth.

The BUF634A can be used in a composite loop (inside the feedback loop of op amps) to increase output current, eliminate thermal feedback, and improve capacitive load drive. See 图 9-7 for this circuit. Decoupling the high-power output current stage from the precision amplifier gives high precision performance by eliminating thermal effects on input offset of the composite circuit. With a large slew rate of 3750 V/µs, the BUF634A can quickly reproduce its input signal at its output without adding considerable delay when used in a composite loop. When used in a composite loop, the outer amplifier controls the circuit precision and distortion performance and the buffer augments the circuit output current drive capability.

See the *节 8.2* for a simplified circuit diagram of the open-loop complementary follower design of the BUF634A.

8.2 Functional Block Diagram



Stage currents are set by I_1.

8.3 Feature Description

8.3.1 Output Current

The BUF634A can deliver up to ±250-mA continuous output current. Internal circuitry limits the output current to approximately ±350 mA. Care must be taken to limit the output voltage swing for a given load resistance to avoid limiting the output current and degrading linearity; see 图 9-8. For many applications, however, the continuous output current is limited by thermal effects. The output voltage swing capability varies with junction temperature and output current; see 图 7-17 and 图 7-18. Care must be taken to operate the device below the maximum-recommended junction temperature in applications using this buffer in wide-bandwidth mode with a wide supply voltage and large output current to avoid permanent damage to the device.

8.3.2 Thermal Shutdown

Power dissipated in the BUF634A causes the junction temperature to rise. A thermal protection circuit in the BUF634A disables the output when the junction temperature reaches approximately 180°C. When the thermal protection is activated, the output stage is disabled and the output current is limited, allowing the device to cool. Quiescent current is approximately 12 mA during thermal shutdown. When the junction temperature cools to approximately 160°C, the output circuitry is again enabled. This process can cause the protection circuit to cycle on and off with a period ranging from a fraction of a second to several minutes or more, depending on package type, signal, load, and thermal environment.

The thermal protection circuit is designed to prevent damage during abnormal conditions. Any tendency to activate the thermal protection circuit during normal operation is a sign of an inadequate heat sink or excessive power dissipation for the package type.

8.3.3 ESD Protection

As shown in 图 8-1, all device pins are protected with internal ESD protection diodes to the power supplies. These diodes provide moderate protection to input overdrive voltages above the supplies. The protection diodes can typically support 10-mA continuous currents. Current limiting series resistors must be added at the inputs if common-mode voltages higher than the supply voltages are possible. Keep these resistor values as low as possible because using high values degrades noise performance and frequency response. V_{IN} is a non fail-safe pin. Ensure V+ and V – are powered up before applying a signal to the V_{IN} pin. Failure to do so results in current flowing through the ESD diode. Restrict any current flowing through the ESD diodes to less than 10 mA.

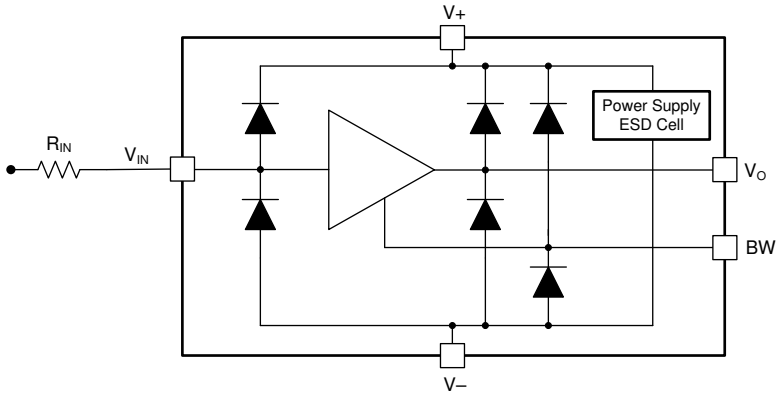


图 8-1. Internal ESD Protection

Copyright © 2021 Texas Instruments Incorporated

8.4 Device Functional Modes

8.4.1 Adjustable Bandwidth

The BUF634A –3-dB bandwidth can be adjusted from 35 MHz to 210 MHz for a 1-kΩ load resistance, as shown in 图 8-2, by connecting a resistor between the V– and BW pins. The bandwidth is set to 210 MHz with the BW pin connected to V– and to 35 MHz with the BW pin left floating. The –3-dB bandwidth also changes with the value of the load resistance for a given bandwidth adjustment resistance. The device quiescent current varies from 1.5 mA (typical) to 8.5 mA (typical) with variation in bandwidth from 35 MHz to 210 MHz, respectively.

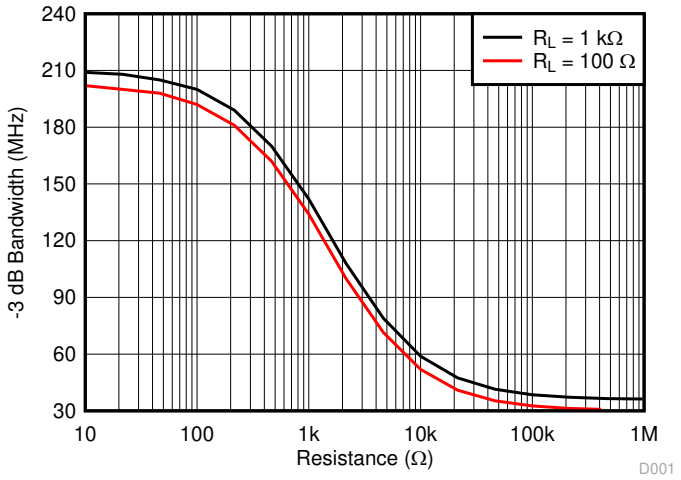


图 8-2. Small-Signal Bandwidth versus Bandwidth Adjustment Resistance

Copyright © 2021 Texas Instruments Incorporated

9 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

图 9-1 shows the BUF634A connected as an open-loop buffer. The source impedance and optional input resistor, R_S, influence the frequency response; see 图 7-3. Bypass the power supplies with capacitors connected close to the device pins. Capacitor values as low as 0.1 µF assure stable operation in most applications, but high output current and fast output slewing can demand large current transients from the power supplies, requiring the use of solid tantalum 10-µF capacitors. High-frequency, open-loop applications benefit from special bypassing and layout considerations. See the *节 9.1.1* for more information. If the BUF634A input is left floating, the device output can swing to either of the supplies based on the input bias current polarity.

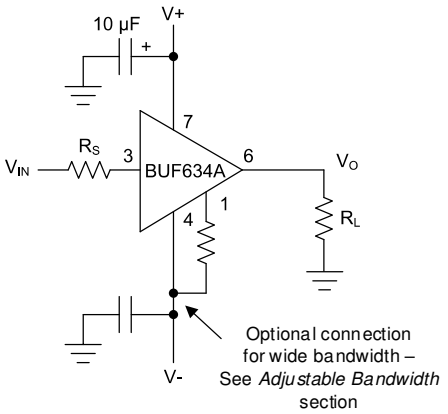


图 9-1. Buffer Connections

9.1.1 High-Frequency Applications

The excellent bandwidth and fast slew rate of the BUF634A are useful in a variety of high-frequency, open-loop applications. When operated in an open-loop application, printed circuit board (PCB) layout and bypassing techniques can affect dynamic performance. 图 9-2 through 图 9-6 illustrate various application circuit examples for the BUF634A.

For best results, use a ground-plane-type circuit board layout and bypass the power supplies with 0.1-µF ceramic chip capacitors at the device pins in parallel with solid tantalum 10-µF capacitors. Source resistance affects high-frequency peaking, step-response overshoot, and ringing. Best response is usually achieved with a series input resistor of 25 Ω to 200 Ω, depending on the signal source. Response with some loads (especially capacitive) can be improved with a resistor of 10 Ω to 150 Ω in series with the output. When driving multiple device under test (DUT) inputs in automatic test equipment (ATE) testers (large capacitive load), as illustrated in 图 9-3, place an isolation resistor at the output of the BUF634A for adequate phase margin and stability.

Copyright © 2021 Texas Instruments Incorporated

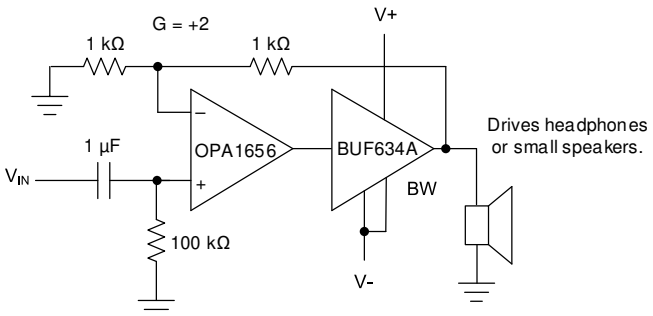


图 9-2. High-Performance Headphone Driver

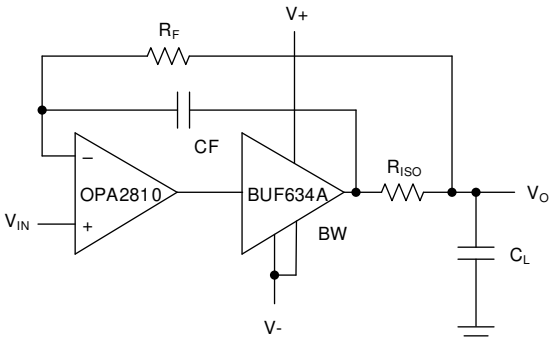


图 9-3. ATE and Test Pin Driver

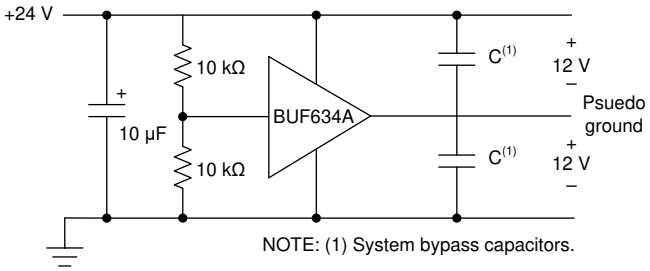


图 9-4. Pseudo-Ground Driver

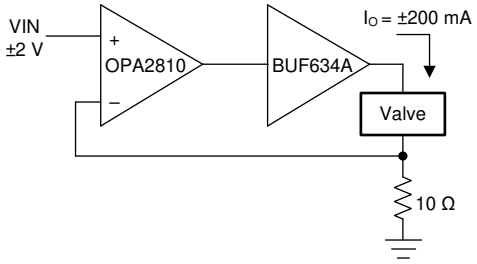


图 9-5. Current-Output Valve Driver

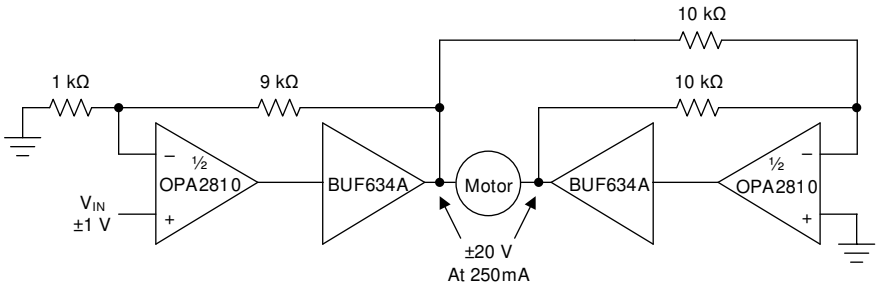
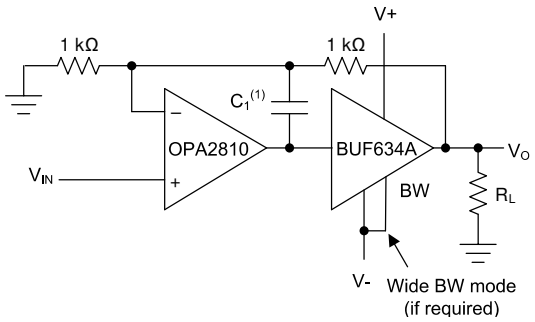


图 9-6. Bridge-Connected Motor Driver

9.2 Typical Application

The BUF634A device can be connected inside the feedback loop, as shown in 图 9-7, of most op amps to increase output current. When connected inside the feedback loop, the offset voltage of the BUF634A and other errors are corrected by the open-loop gain and feedback of the op amp.



C_1 is not required for most common op amps. Use C_1 with unity-gain stable, high-speed op amps.

图 9-7. Boosting Op Amp Output Current

9.2.1 Design Requirements

- Boost the output current of an OPA2810
- Operate from ±12-V power supplies
- Operate from –40°C to +125°C
- Gain = 2 V/V
- Output current = ±250 mA
- Bandwidth greater than 100 kHz

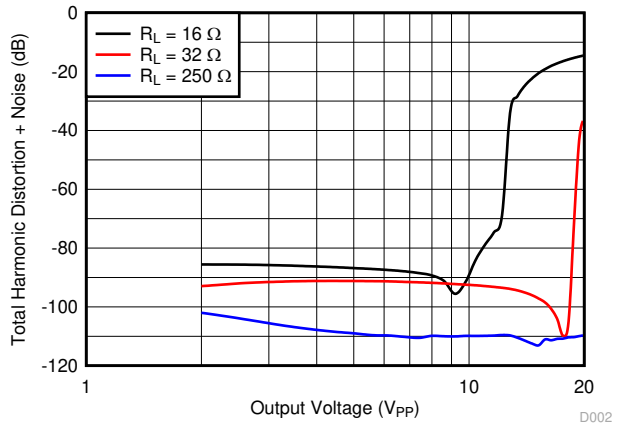
Copyright © 2021 Texas Instruments Incorporated

9.2.2 Detailed Design Procedure

To assure that the composite amplifier remains stable, the phase shift of the BUF634A must remain small throughout the loop gain of the circuit. For a G = +1 op-amp circuit, the BUF634A must contribute little additional phase shift (approximately 20° or less) at the unity-gain frequency of the op amp. Phase shift is affected by various operating conditions that can affect the stability of the op amp.

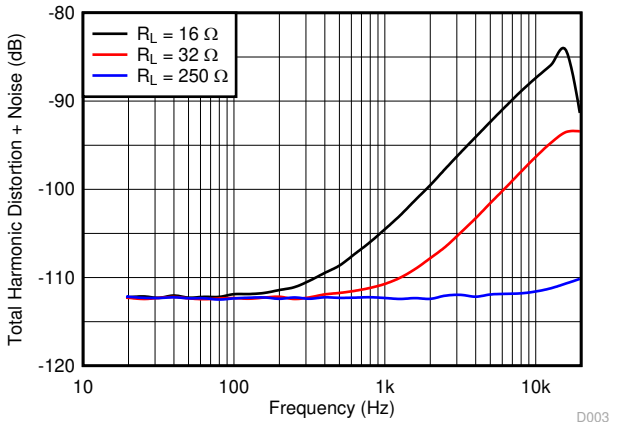
For the circuit in 图 9-7, most general-purpose or precision op amps remain unity-gain stable with the BUF634A connected inside the feedback loop. Large capacitive loads may require the BUF634A to be connected for wide bandwidth for stable operation. High-speed or fast-settling op amps generally require wide-bandwidth mode to remain stable and to assure good dynamic performance. Check for oscillations or excessive ringing on signal pulses with the intended load and worst-case conditions that affect phase response of the buffer to determine stability with an op amp. Connect the circuit as shown in 图 9-7. Choose resistors to provide a voltage gain of 2 V/V. Select the feedback resistor to be 1 kΩ. Choose the input resistor to be 1 kΩ and C_1 to be 10 pF. 图 9-8 and 图 9-9 illustrate the THD+N plots for the BUF634A used with the OPA2810 in a gain of 2-V/V composite loop. The THD+N performance is superior in a composite loop when compared with a standalone BUF634A because of the negative feedback and open-loop gain of the OPA2810. In 图 9-8, the signal distortion degrades for large output voltages with 16-Ω and 32-Ω loads because of the device internal short-circuit protection.

9.2.3 Application Curves



f = 20 kHz, 90-kHz measurement bandwidth

图 9-8. THD+N vs Output Voltage Using the BUF634A with the OPA2810



V_O = 10 V_{PP}, 90-kHz measurement bandwidth

图 9-9. THD+N vs Frequency Using the BUF634A with the OPA2810

Copyright © 2021 Texas Instruments Incorporated

10 Power Supply Recommendations

The BUF634A is intended for operation on supplies ranging from 4.5 V to 36 V (±2.25 V to ±18 V). At low power-supply conditions, such as ±2.25 V, the output swing may be limited. See the output voltage range specifications in the *Electrical Characteristics* tables for additional information. The BUF634A can be operated on single-sided supplies, split, and balanced bipolar supplies or unbalanced bipolar supplies. Operating from a single supply can have numerous advantages. With the negative supply at ground, the DC errors resulting from the –PSRR term can be minimized. Minimize the distance (< 0.1 in.) from the power-supply pins to high-frequency, 0.1-µF decoupling capacitors. A larger capacitor (10 µF typical) is used along with a high-frequency, 0.1-µF supply-decoupling capacitor at the device supply pins. For single-supply operation, only the positive supply has these capacitors. When a split-supply is used, use these capacitors from each supply to ground. If necessary, place the larger capacitors further from the device and share these capacitors among several devices in the same area of the PCB.

10.1 Power Dissipation and Thermal Considerations

The BUF634A includes automatic thermal shutoff protection. This protection circuitry shuts down the amplifier if the junction temperature exceeds approximately 180°C. When the junction temperature decreases to approximately 160°C, the buffer turns on again. The package and the PCB dictate the thermal characteristics of the device. Maximum power dissipation for a particular package is calculated using the following formula.

$$P_{Dmax} = \frac{T_{max} - T_A}{\theta_{JA}} \quad (1)$$

where

- PD_{max} is the maximum power dissipation in the amplifier (W).
- T_{max} is the absolute maximum junction temperature (°C).
- T_A is the ambient temperature (°C).
- $\theta_{JA} = \theta_{JC} + \theta_{CA}$
- θ_{JC} is the thermal coefficient from the silicon junctions to the case (°C/W).
- θ_{CA} is the thermal coefficient from the case to ambient air (°C/W).

The thermal coefficient for the thermal pad integrated circuit packages are substantially improved over the traditional SOIC package. The data for the thermal pad packages assume a board layout that follows the thermal pad package layout guidelines referenced above and detailed in the *PowerPAD™ Thermally Enhanced Package* application report. If the thermal package integrated circuit package is not soldered to the PCB, the thermal impedance increases substantially and may cause serious heat and performance issues.

When determining whether or not the device satisfies the maximum power dissipation requirement, make sure to consider not only quiescent power dissipation, but dynamic power dissipation. Often times, this dissipation is difficult to quantify because the signal pattern is inconsistent, but an estimate of the RMS power dissipation provides visibility into a possible problem.

Copyright © 2021 Texas Instruments Incorporated

11 Layout

11.1 Layout Guidelines

11.1.1 SOIC Layout Guidelines (D Package Without a Thermal Pad)

For best operational performance of the device, use good PCB layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit. Bypass capacitors are used to reduce the coupled noise by providing low-impedance power sources local to the analog circuitry.
  - Connect low-ESR, 0.1-µF ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for single-supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most effective methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes. A ground plane helps distribute heat and reduces electromagnetic interference (EMI) noise pickup. Make sure to physically separate digital and analog grounds, paying attention to the flow of the ground current.
- In order to reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If these traces cannot be kept separate, crossing the sensitive trace perpendicular is much better as opposed to in parallel with the noisy trace.
- Place the external components as close to the device as possible, as illustrated in 图 11-2.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Cleaning the PCB following board assembly is recommended for best performance.
- Any precision integrated circuit can experience performance shifts resulting from moisture ingress into the plastic package. Following any aqueous PCB cleaning process, baking the PCB assembly is recommended to remove moisture introduced into the device packaging during the cleaning process. A low-temperature, post-cleaning bake at 85°C for 30 minutes is sufficient for most circumstances.

The SOIC-8 surface-mount package is excellent for applications requiring high output current with low average power dissipation. To achieve the best possible thermal performance with the SOIC-8 package, solder the device directly to a circuit board. Sockets degrade thermal performance because much of the heat is dissipated by conduction through the package pins. Use wide circuit board traces on all device pins, including pins that are not connected. For more information on designing the circuit board, see the *BUF634AD Evaluation module* user's guide.

Copyright © 2021 Texas Instruments Incorporated

11.1.2 HSOIC Layout Guidelines (DDA Package With a Thermal Pad)

图 11-1 shows the DDA package top-side etch and via pattern.

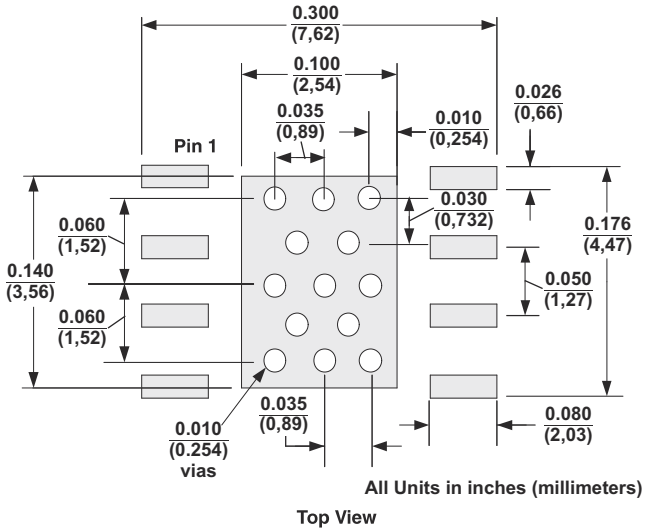


图 11-1. DDA Thermal Pad Integrated Circuit Package PCB Etch and Via Pattern

1. Use an etch for the leads and the thermal pad.
2. Place 13 vias in the thermal pad area. These vias must be 0.01 inch (0.254 mm) in diameter. Keep the vias small so that solder wicking through the vias is not a problem during reflow.
3. Additional vias may be placed anywhere along the thermal plane outside of the thermal pad area, and help dissipate the heat generated by the BUF634A. These additional vias may be larger than the 0.01-inch (0.254 mm) diameter vias directly under the thermal pad because they are not in the area that requires soldering. As a result, wicking is not a problem.
4. The thermal pad is internally connected with V – . Therefore, always short the thermal pad to the same potential as V – externally as well.
5. Connect all vias used under the thermal pad to remove heat to the V – plane.
6. When connecting these vias to the V – plane, do not use the typical web or spoke connection methodology. Web and spoke connections have a high thermal resistance that slows the heat transfer during soldering. The vias under the BUF634A thermal pad must connect to the internal thermal plane or thermal pour with a complete connection around the entire circumference of the plated-through hole.
7. The top-side solder mask must leave the pins of the package and the thermal pad area with the 13 vias exposed.
8. Apply solder paste to the exposed thermal pad area and all of the device pins.
9. With these preparatory steps in place, the device is placed in position and run through the solder reflow operation as any standard surface-mount component.

Copyright © 2021 Texas Instruments Incorporated

11.2 Layout Example

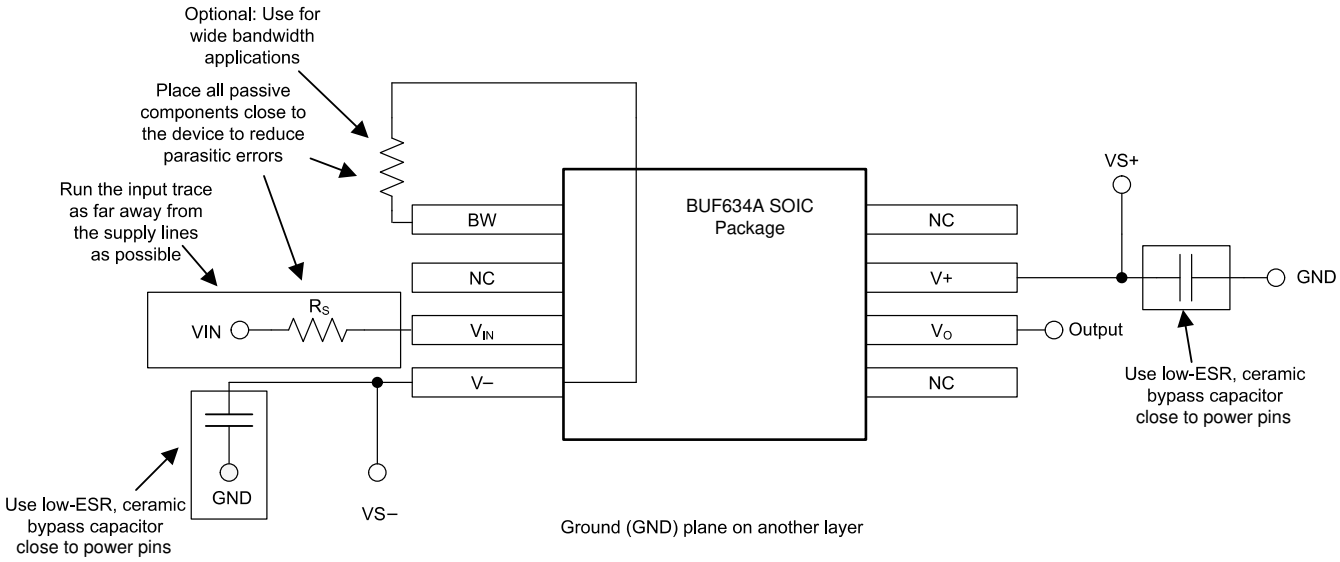


图 11-2. BUF634A Layout Example (SOIC)

12 Device and Documentation Support

12.1 Device Support

12.1.1 第三方产品免责声明

TI 发布的与第三方产品或服务有关的信息，不能构成与此类产品或服务或保修的适用性有关的认可，不能构成此类产品或服务单独或与任何 TI 产品或服务一起的表示或认可。

12.1.2 Development Support

12.1.2.1 TINA-TI™ (Free Software Download)

TINA™ is a simple, powerful, and easy-to-use circuit simulation program based on a SPICE engine. TINA-TI is a free, fully-functional version of the TINA software, and is preloaded with a library of macromodels in addition to a range of both passive and active models. TINA-TI provides all the conventional DC, transient, and frequency domain analysis of SPICE, as well as additional design capabilities.

Available as a free download from the Analog eLab Design Center, TINA-TI offers extensive post-processing capability that allows users to format results in a variety of ways. Virtual instruments offer the ability to select input waveforms and probe circuit nodes, voltages, and waveforms, creating a dynamic quick-start tool.

Note

These files require that either the TINA software (from DesignSoft™) or TINA-TI software be installed. Download the free TINA-TI software from the TINA-TI folder.

12.1.2.2 TI Precision Designs

The BUF634A is featured in several TI Precision Designs, available online at www.ti.com. TI Precision Designs are analog solutions created by TI's precision analog applications experts and offer the theory of operation, component selection, simulation, complete PCB schematic and layout, bill of materials, and measured performance of many useful circuits.

12.2 Documentation Support

12.2.1 Related Documentation

For related documentation see the following:

- Texas Instruments, *OPA2810 Dual-channel, 27-V, Rail-to-Rail Input/Output FET-Input Operational Amplifier* data sheet
- Texas Instruments, *BUF634AD Evaluation Module* user's guide
- Texas Instruments, *Combining An Amplifier with the BUF634* application note
- Texas Instruments, *Add Current Limit to the BUF634* application note
- Texas Instruments, *Power Amplifier Stress and Power Handling Limitations* application note
- Texas Instruments, *Shelf-Life Evaluation of Lead-Free Component Finishes* application report

12.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.4 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

12.5 Trademarks

TINA-TI™, TINA™, and TI E2E™ are trademarks of Texas Instruments.

Copyright © 2021 Texas Instruments Incorporated

DesignSoft™ is a trademark of DesignSoft, Inc.
所有商标均为其各自所有者的财产。

12.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.7 Glossary

TI Glossary This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Copyright © 2021 Texas Instruments Incorporated

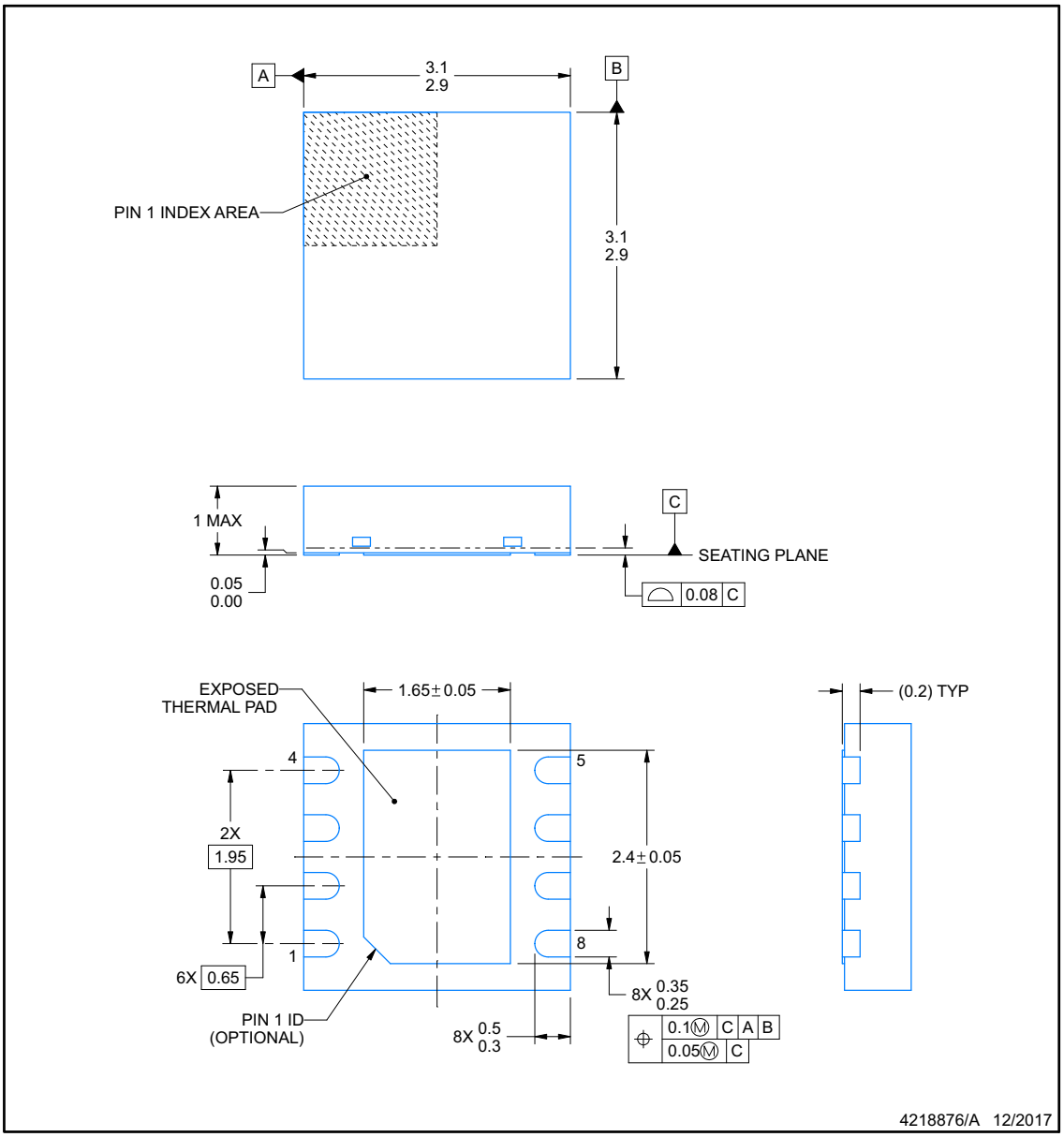
PACKAGE OUTLINE

DRB0008B



VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

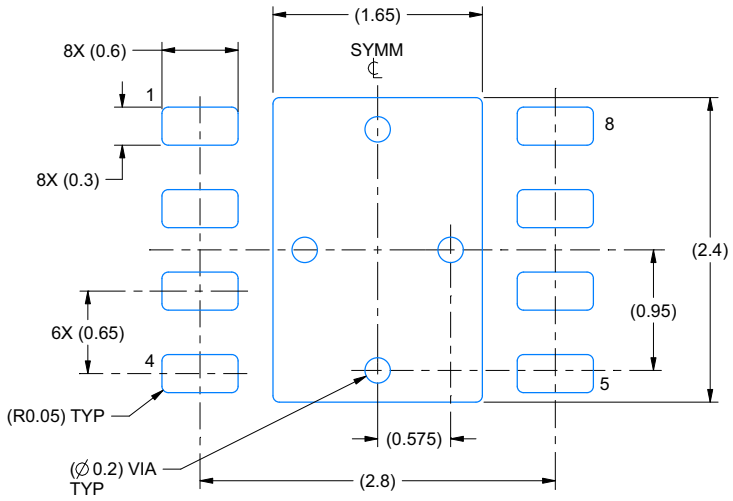
Copyright © 2021 Texas Instruments Incorporated

EXAMPLE BOARD LAYOUT

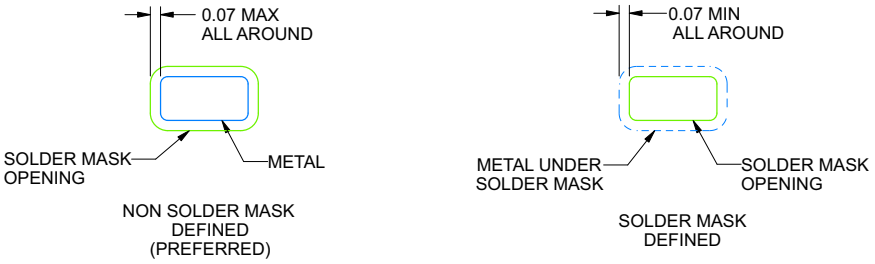
DRB0008B

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
SCALE:20X



SOLDER MASK DETAILS

4218876/A 12/2017

NOTES: (continued)

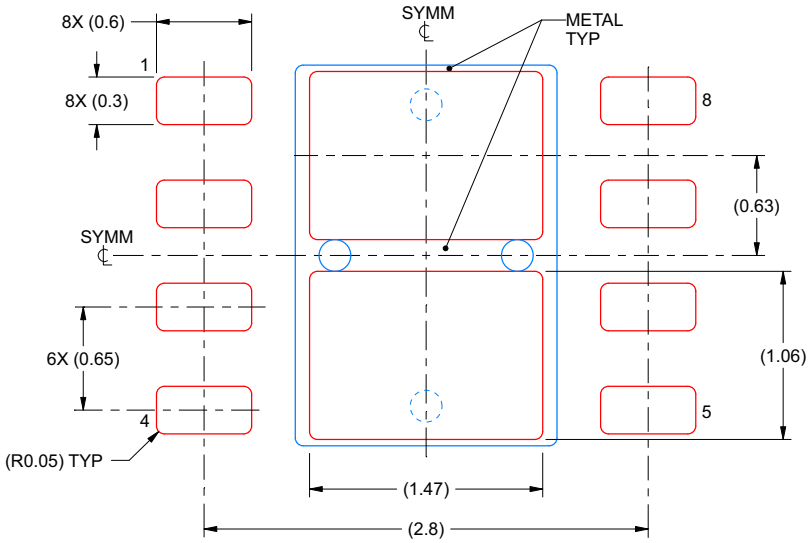
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

Copyright © 2021 Texas Instruments Incorporated

EXAMPLE STENCIL DESIGN

DRB0008B — **VSON - 1 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
81% PRINTED SOLDER COVERAGE BY AREA
SCALE:25X

4218876/A 12/2017

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

Copyright © 2021 Texas Instruments Incorporated

重要声明和免责声明

TI 提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做出任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他安全、安保或其他要求。这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的应用。严禁对这些资源进行其他复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 TI 的销售条款 (https:www.ti.com/legal/termsofsale.html) 或 ti.com 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2021，德州仪器 (TI) 公司

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
BUF634AIDDAR	Active	Production	SO PowerPAD (DDA) | 8	2500 | LARGE T&R	Yes	NIPDAU | NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	BF634A
BUF634AIDDAR.B	Active	Production	SO PowerPAD (DDA) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	BF634A
BUF634AIDR	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	BF634A
BUF634AIDR.B	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	BF634A
BUF634AIDRBR	Active	Production	SON (DRB) | 8	3000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	B634A
BUF634AIDRBR.B	Active	Production	SON (DRB) | 8	3000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	B634A
BUF634AIDRBRG4	Active	Production	SON (DRB) | 8	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B634A
BUF634AIDRBRG4.B	Active	Production	SON (DRB) | 8	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B634A
BUF634AIDRG4	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	BF634A
BUF634AIDRG4.B	Active	Production	SOIC (D) | 8	2500 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	BF634A

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

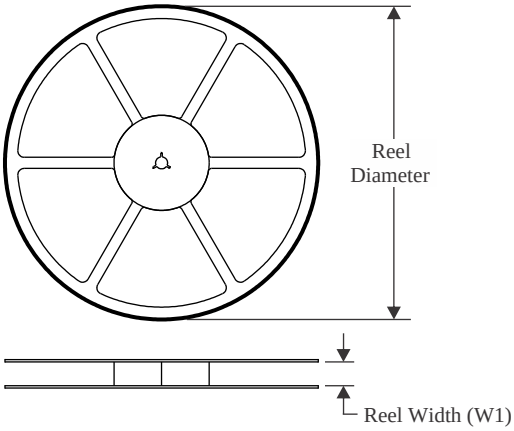
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

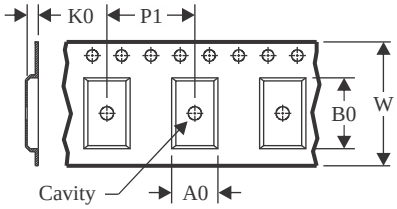
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

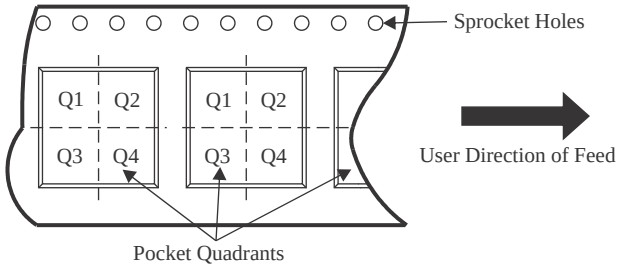


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

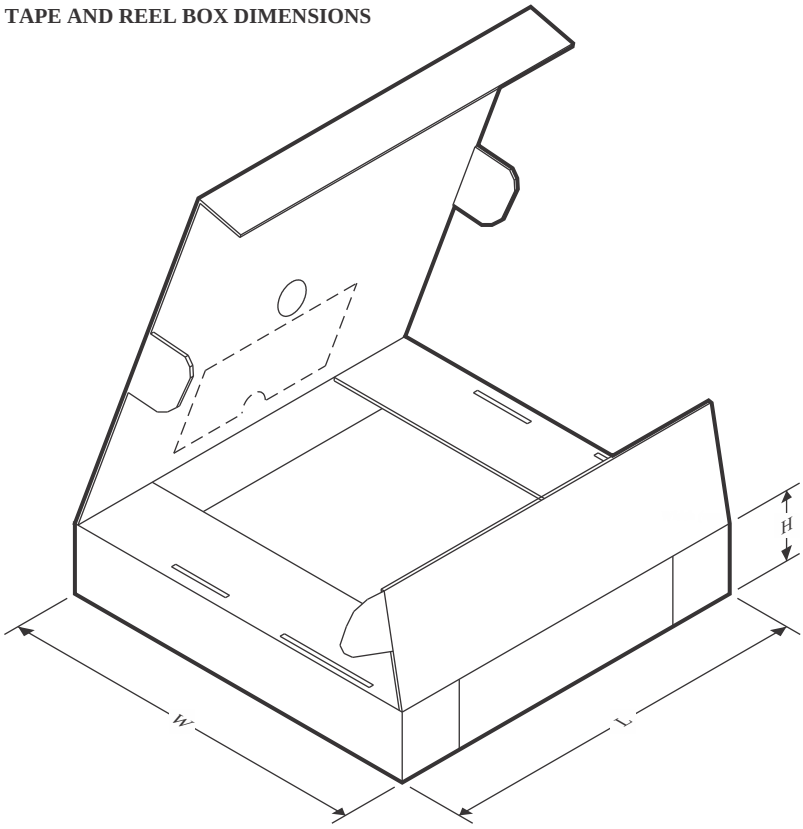
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BUF634AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
BUF634AIDRBR	SON	DRB	8	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BUF634AIDRBRG4	SON	DRB	8	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BUF634AIDRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BUF634AIDR	SOIC	D	8	2500	353.0	353.0	32.0
BUF634AIDRBR	SON	DRB	8	3000	360.0	360.0	36.0
BUF634AIDRBRG4	SON	DRB	8	3000	367.0	367.0	35.0
BUF634AIDRG4	SOIC	D	8	2500	353.0	353.0	32.0

GENERIC PACKAGE VIEW

DRB 8

VSON - 1 mm max height

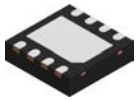
PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4203482/L

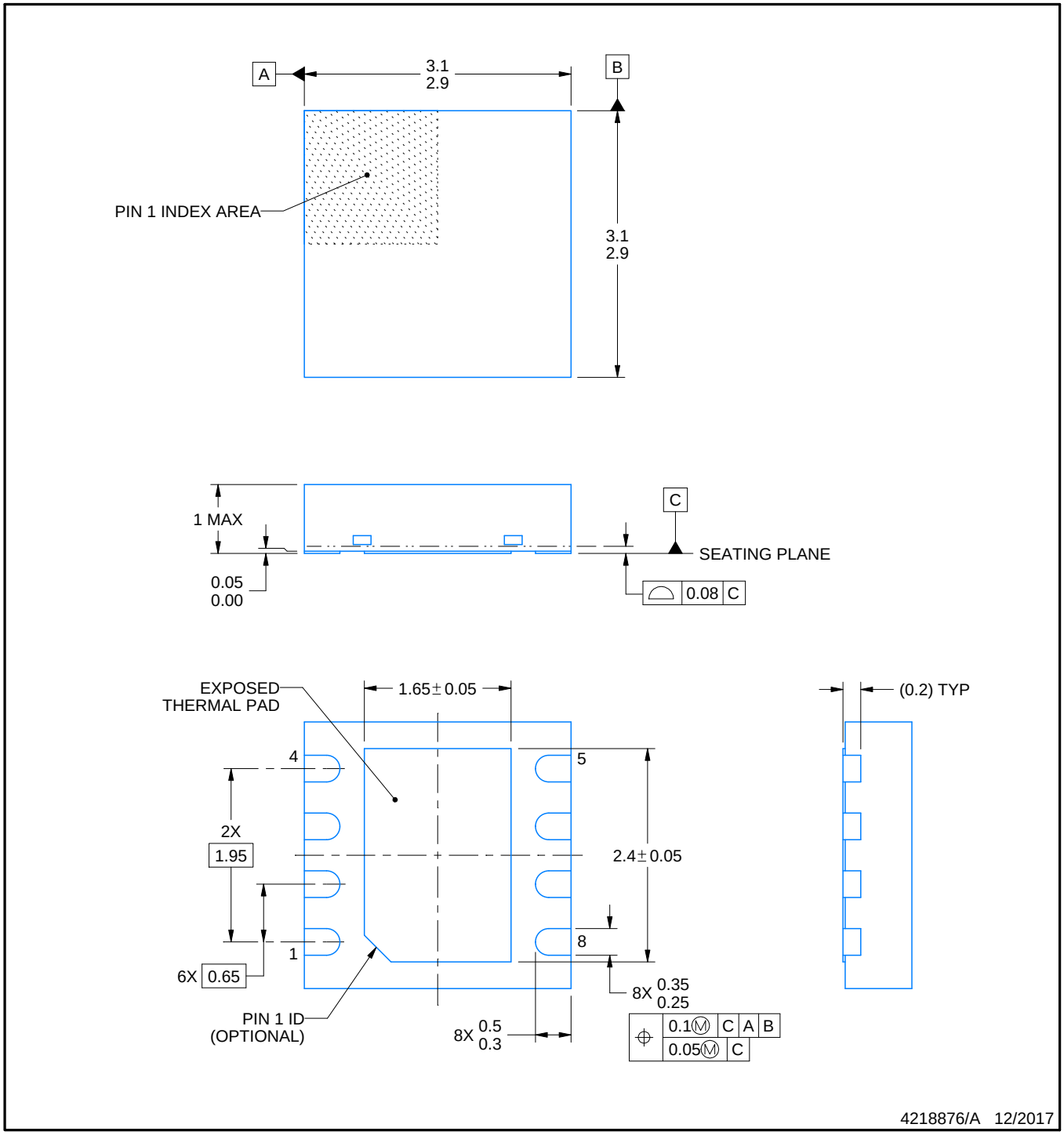
DRB0008B



PACKAGE OUTLINE

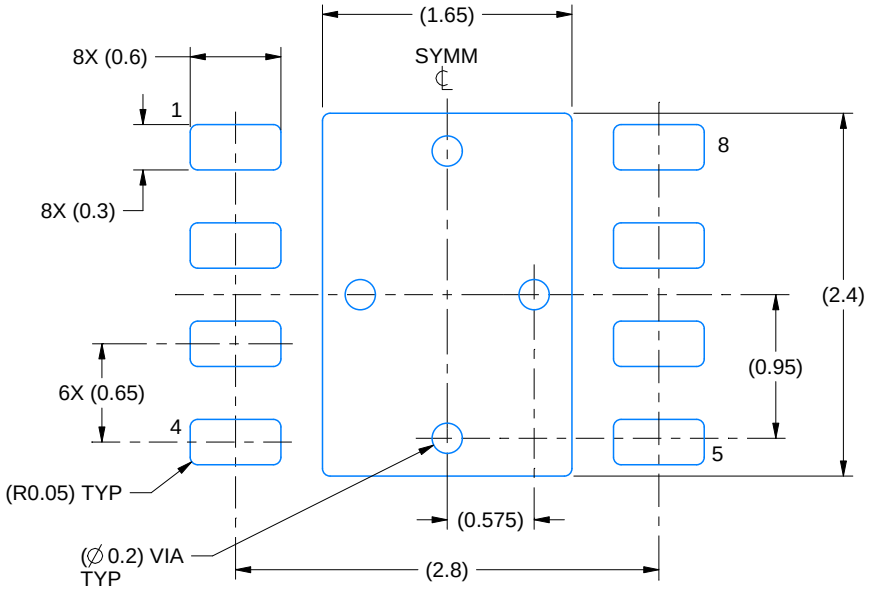
VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

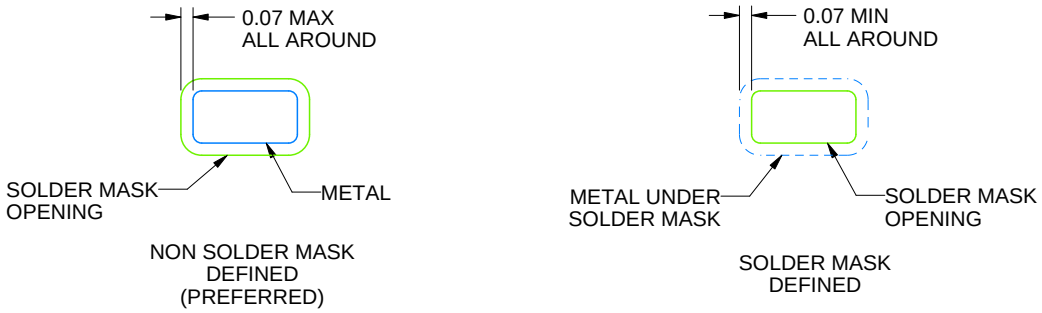


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
SCALE:20X

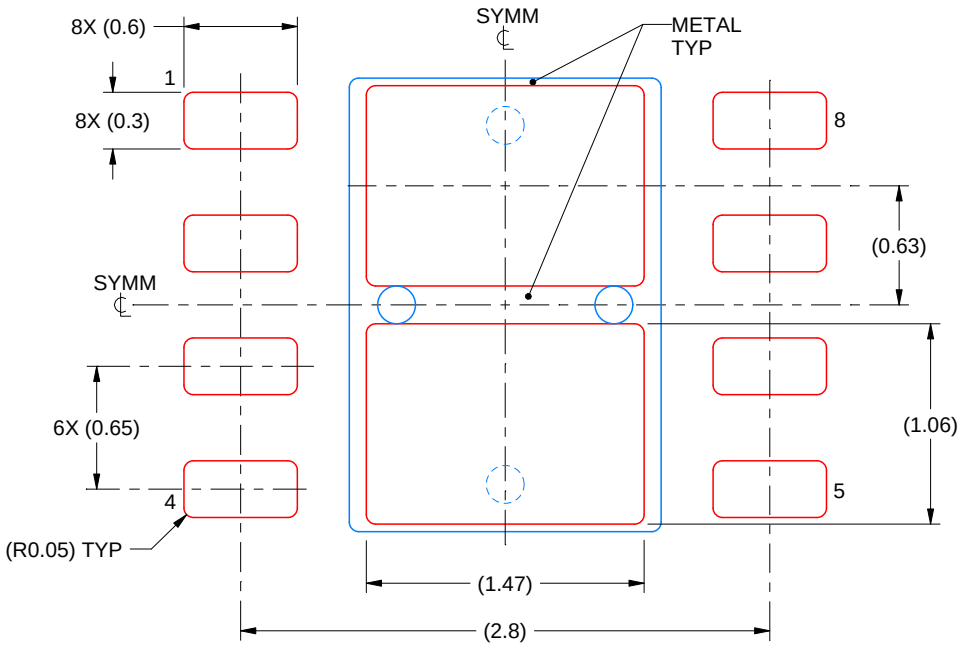


SOLDER MASK DETAILS

4218876/A 12/2017

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
81% PRINTED SOLDER COVERAGE BY AREA
SCALE:25X

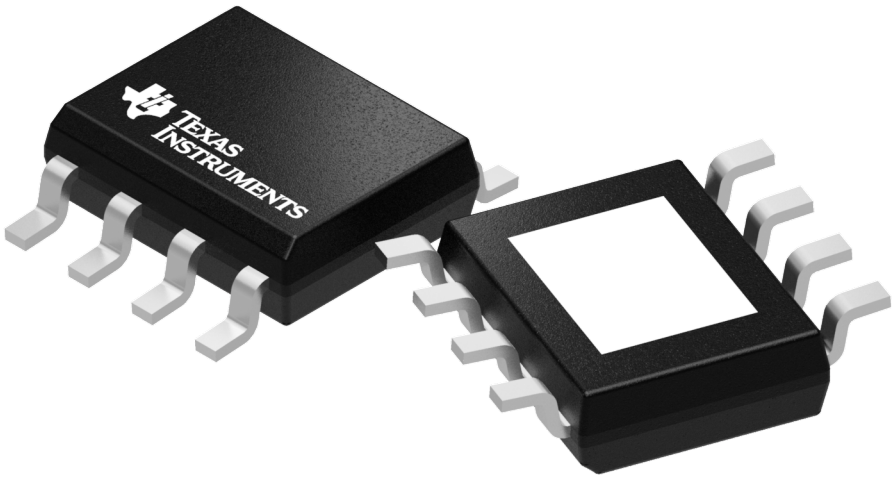
4218876/A 12/2017

NOTES: (continued)

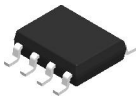
6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

DDA 8 PowerPAD™ SOIC - 1.7 mm max height

PLASTIC SMALL OUTLINE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

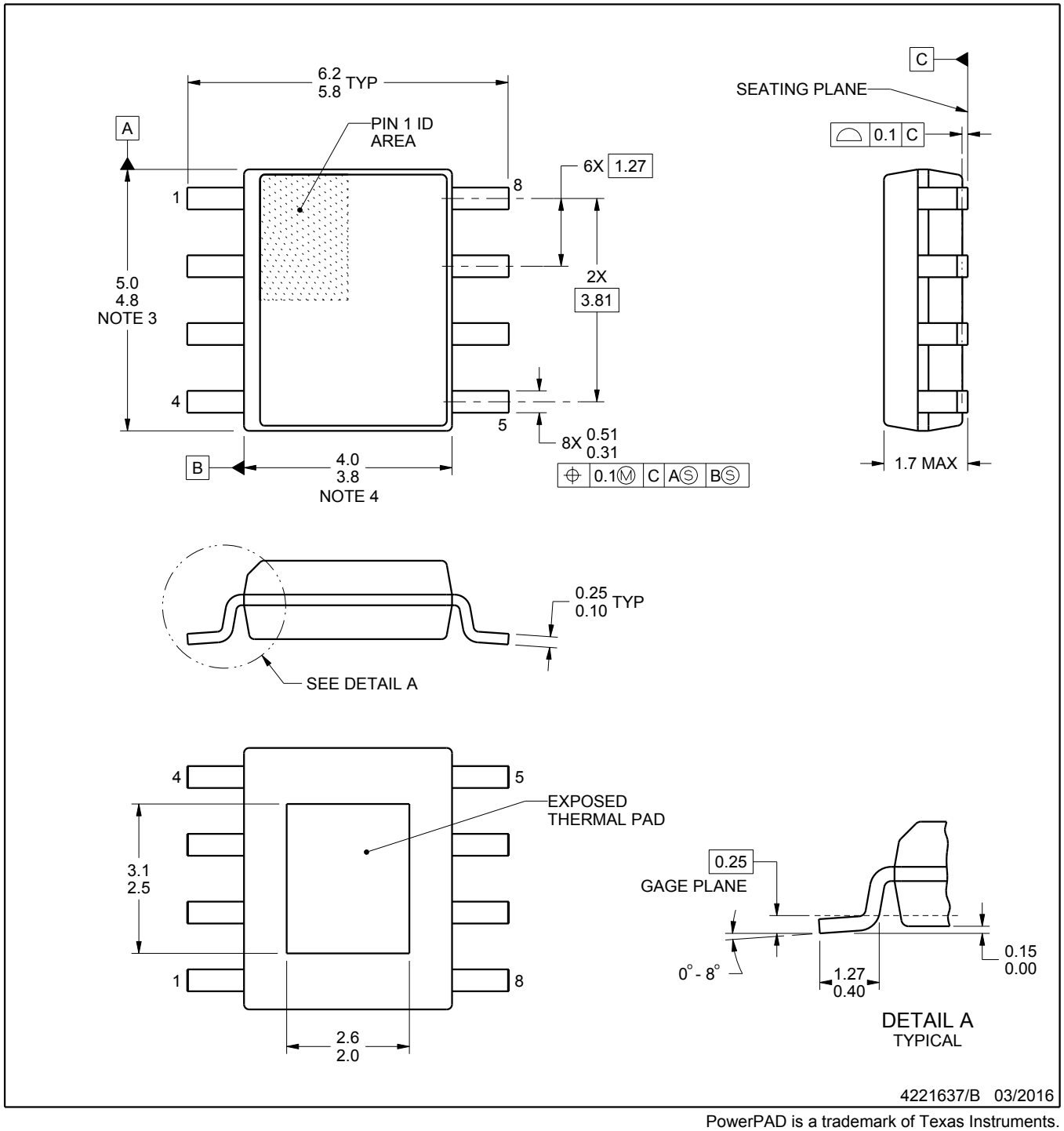


PACKAGE OUTLINE

DDA0008J

PowerPAD™ SOIC - 1.7 mm max height

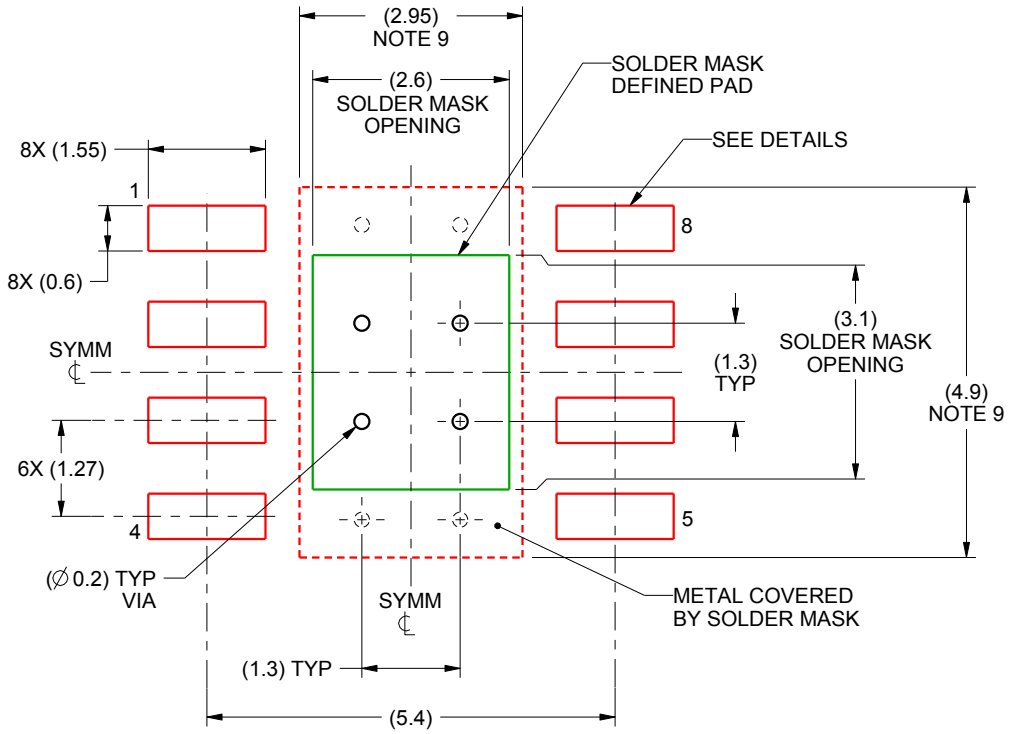
PLASTIC SMALL OUTLINE



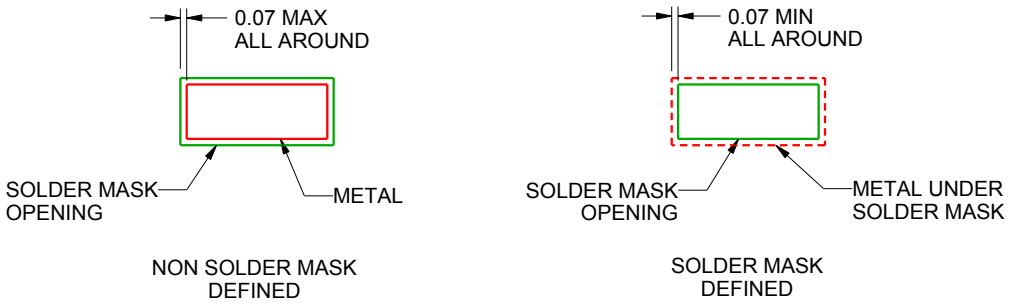
PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MS-012, variation BA.



LAND PATTERN EXAMPLE
SCALE:10X

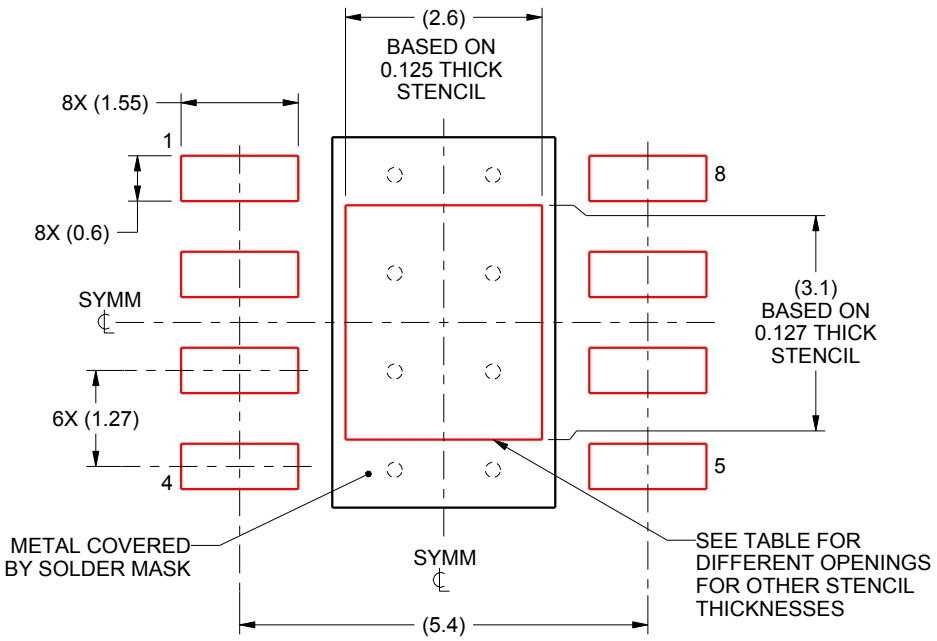


SOLDER MASK DETAILS

4221637/B 03/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.



SOLDER PASTE EXAMPLE
EXPOSED PAD
100% PRINTED SOLDER COVERAGE BY AREA
SCALE:10X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	2.91 X 3.47
0.125	2.6 X 3.1 (SHOWN)
0.150	2.37 X 2.83
0.175	2.20 X 2.62

4221637/B 03/2016

NOTES: (continued)

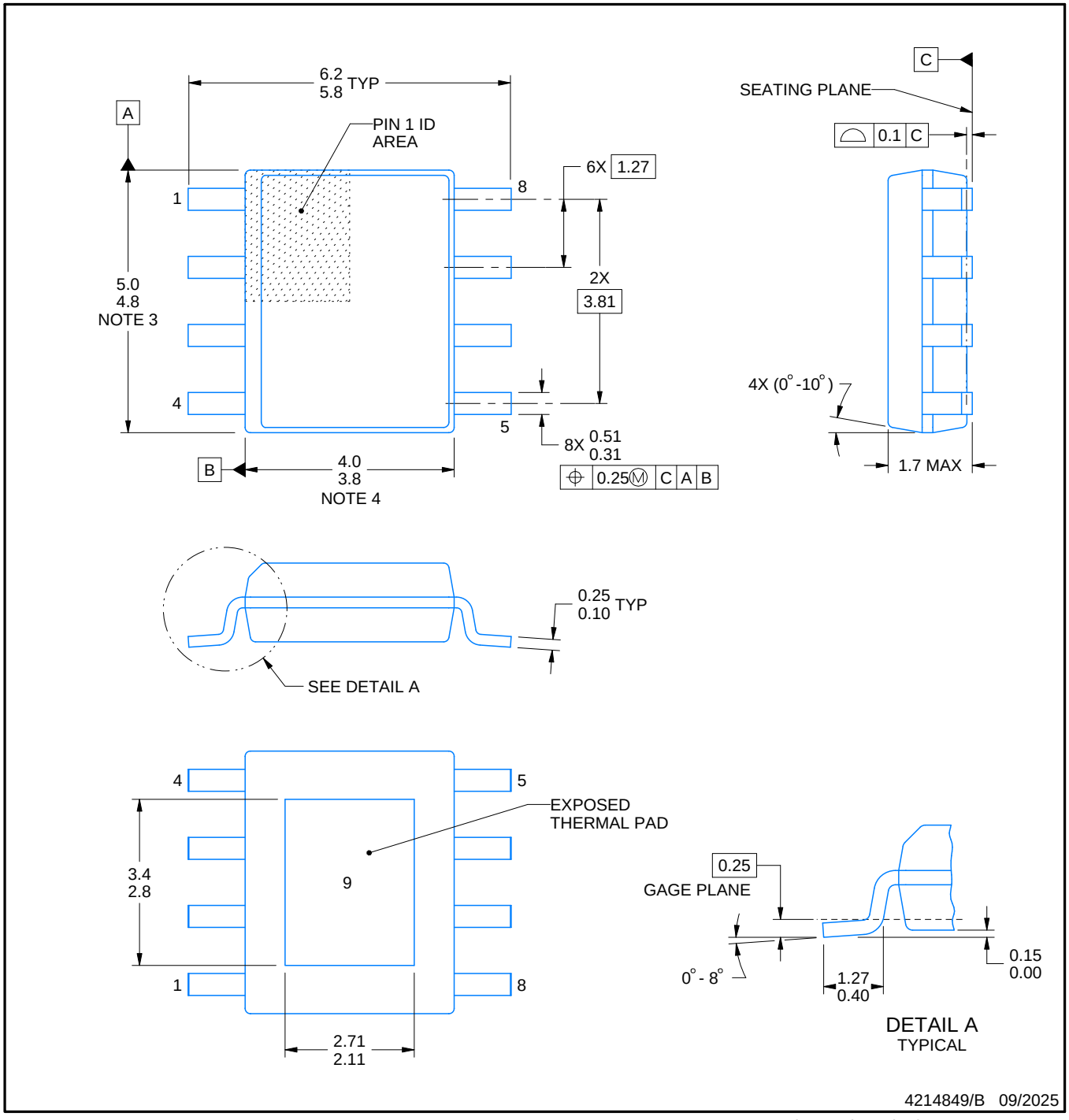
10. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
11. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DDA0008B

PowerPAD™ SOIC - 1.7 mm max height

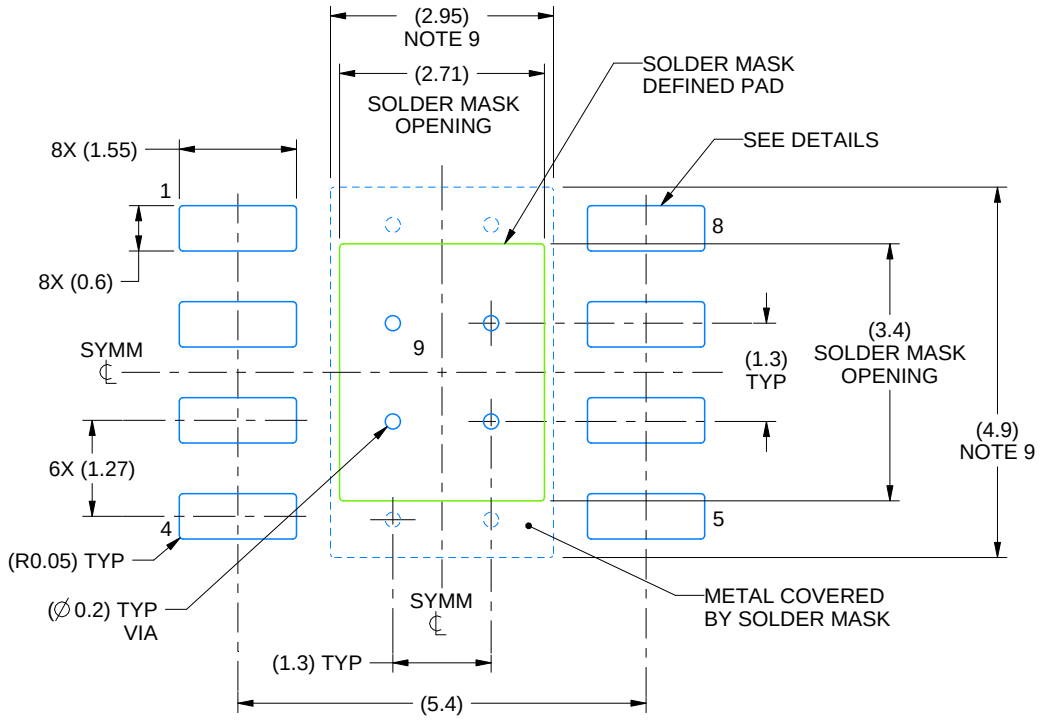
PLASTIC SMALL OUTLINE



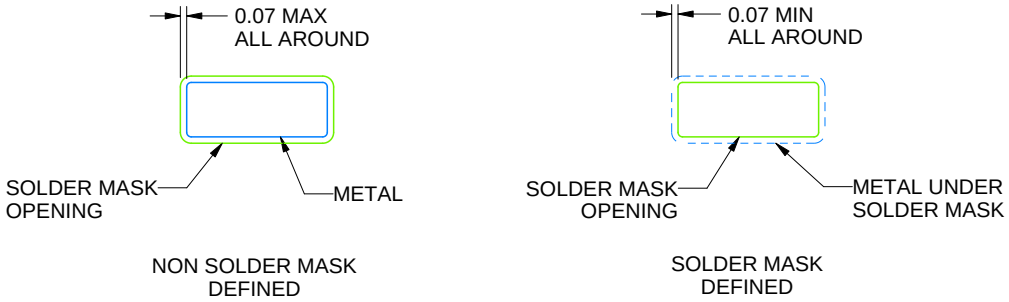
PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MS-012.



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
PADS 1-8

4214849/B 09/2025

NOTES: (continued)

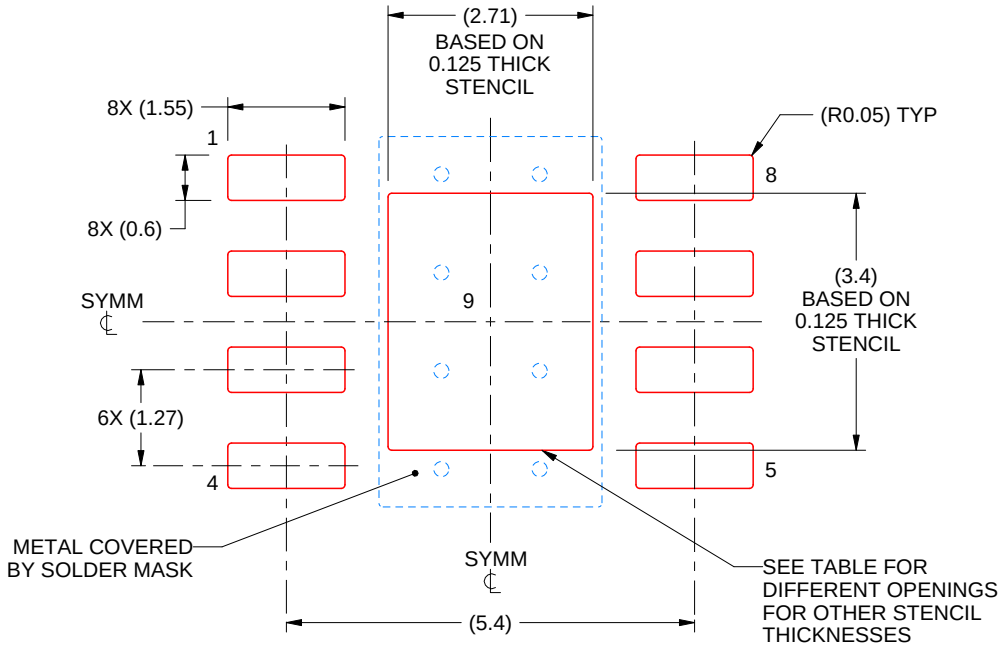
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DDA0008B

PowerPAD™ SOIC - 1.7 mm max height

PLASTIC SMALL OUTLINE



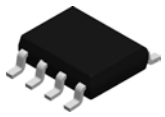
SOLDER PASTE EXAMPLE
EXPOSED PAD
100% PRINTED SOLDER COVERAGE BY AREA
SCALE:10X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	3.03 X 3.80
0.125	2.71 X 3.40 (SHOWN)
0.150	2.47 X 3.10
0.175	2.29 X 2.87

4214849/B 09/2025

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

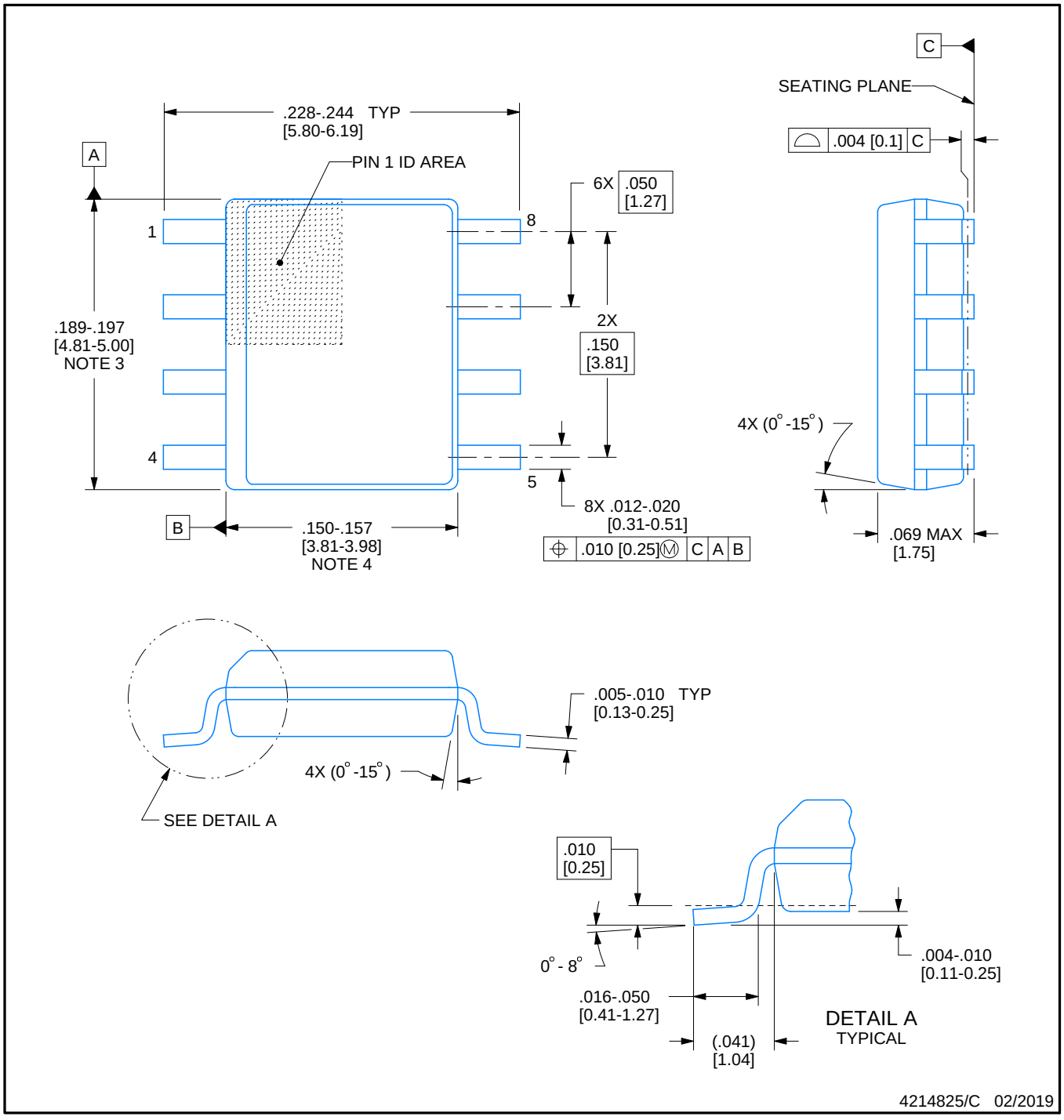


PACKAGE OUTLINE

D0008A

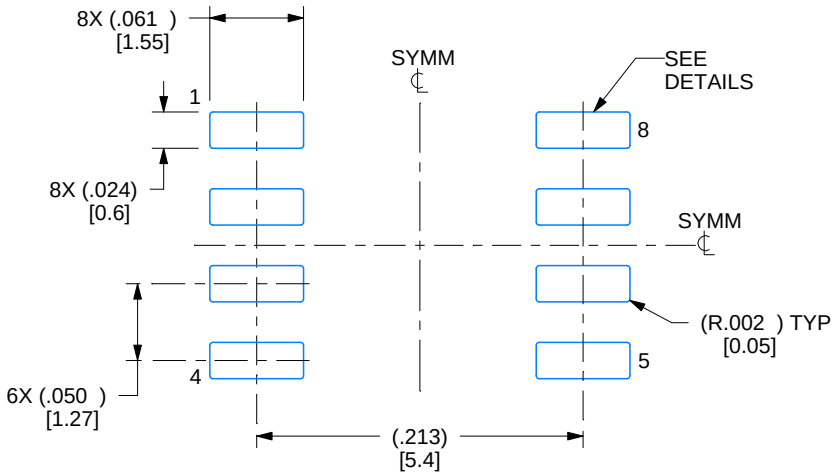
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

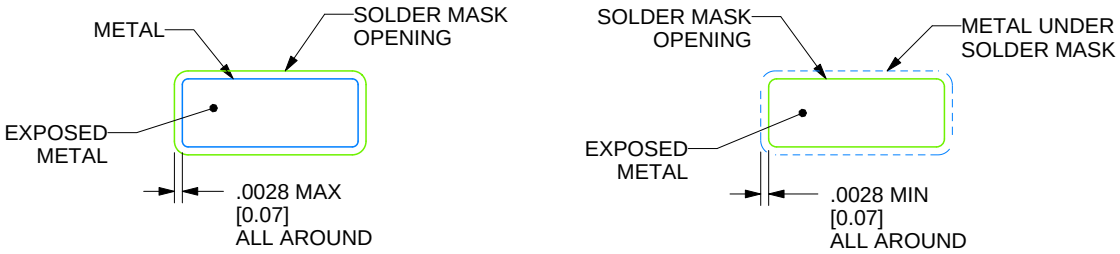


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

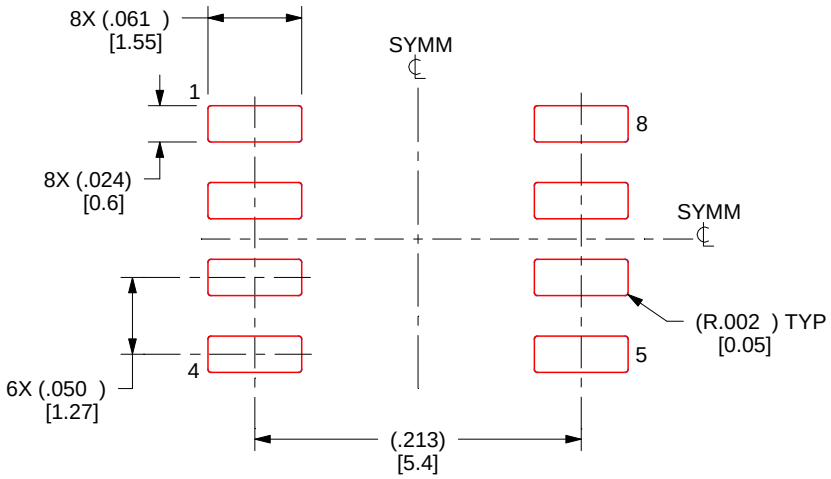
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要通知和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做出任何明示或暗示的担保，包括但不限于对适销性、与某特定用途的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他安全、安保法规或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的相关应用。严禁以其他方式对这些资源进行复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。对于因您对这些资源的使用而对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，您将全额赔偿，TI 对此概不负责。

TI 提供的产品受 TI 销售条款)、TI 通用质量指南 或 ti.com 上其他适用条款或 TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。 除非德州仪器 (TI) 明确将某产品指定为定制产品或客户特定产品，否则其产品均为按确定价格收入目录的标准通用器件。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

版权所有 © 2026，德州仪器 (TI) 公司

最后更新日期：2025 年 10 月